Paper ID	Authors	Title	Track	Decision
4	Chen Chao Wang	Fan-out Chip on Substrate (FOCoS) Development for HPC and AI applications	Advanced Packaging	ACCEPT
7	Kui Li, Zihang Yuan, Chao Zhao, Yanmei Kong, Ruiwen Liu, Binbin Jiao and Gao Wu	A Low-Thermal-Resistance Packaging Technology in multi-chip Microsystem	Quality & Reliability	ACCEPT
8	Wentao Dou, Jw Seah, Vk Leong, Jingwei Sun, Bin Zhou, Lizhi Chen, Shijian Zhou, Qingnan Shi, Tengteng He and Feng Zhang	Revolutionizing Wafer-Level Chip-Scale Packaging: Advanced Die Chipping Solutions Using Laser Grooving and Plasma Dicing	Advanced Packaging	ACCEPT
9	Lois Liao, Zuohua Yu, Guoshun Wu, Xi Zhang, Lei Zhu, Younan Hua and Xiaomin Li	Comparison of moisture penetration speed in two types of SOP	Quality & Reliability	ACCEPT
11	Hanshi Wang, Shaogang Wang, Ke Liu, Huaiyu Ye and Chunjian Tan	Improvement on the short-circuit Performance of SiC MOSFET with different shapes and materials of the dielectric layer	Power Electronics	ACCEPT
12	Younan Hua, Lois Jinzhi and Xiaomin Li	Studies of Silicon Crystalline Defects Delineation Method and Application in Failure Analysis	Quality & Reliability	ACCEPT
14	Jiahao Liu, Dangyang Tian, Lijin Qiu and Fangzhou Chen	The influence of interconnect layer cavity on the thermal resistance of power devices	Quality & Reliability	ACCEPT
15	Liu Chu, Jiajia Shi and Eduardo Souza de Cursi	Robustness of inhomogeneous sparse ball grid array (BGA) in electronic packaging for uncertainty in material properties	Quality & Reliability	ACCEPT
16	Gao Fubin, Li Kunpeng and Pan Jiannan	High-Density Interconnect Technology for LTCC Substrates in High-Reliability Hybrid Integrated Circuits	Packaging Materials & Processes	ACCEPT
18	一鸣 郝, 思 陈, 飞 秦 and 潮 李	EVOLUTION ANALYSIS OF RESIDUAL STRESS IN CU-SIO2 HYBRID BONDING DURING BONDING PROCESS	Quality & Reliability	ACCEPT
19	Fa-Chuan Chen, Chien-Min Lin, Yin-Fa Chen, Bo-Kuan Yeh, Hsin-Long Chen, Yu-Hsing Lin, Che-Kuan Chu, Tai-Yin Lin and Zhe-Cheng Xu	Investigation of Polyimide Cracking Effects in Wafer-Level Chip Scale Package on Substrate (WLCSPoS) During Component-Level and Board-Level Reliability Testing	Quality & Reliability	ACCEPT
20	Liu Chu, Jiajia Shi and Eduardo Souza de Cursi	An adaptive finite volume model (FVM) for heterogeneous interconnects in electronic packaging	Packaging Design & Modeling	accept?
21	Qiang Wei, Weidong Liu, Xiaojian Ma, Huan Yang, Jiachen Wang and Pengkai Wang	Simulation analysis and verification of warpage in reflow of large-size BGA product	Packaging Design & Modeling	ACCEPT
22	Wei Lin, Yanbo Tang, Boping Wu and Shangru Han	Influence of Transmission Line Length and Error Analysis in the Transmission Line Method for Dielectric Constant Extraction in Packaging Materials	Packaging Materials & Processes	ACCEPT

Paper ID	Authors	Title	Track	Decision
23	Haodi Ren, Zhentao Yang, Fei Yu, Yongchao Chen and Linjie Liu	Research on the miniaturisation of the Ceramic Quad Flat Package (CQFP): Development of claw-shaped lead structure	Packaging Design & Modeling	ACCEPT
28	Dongyang Tian, Jiahao Liu, Xiangjun Lu and Bin Zhou	Research on EBSD parameter optimization based on multi-method collaboration and its application in TSV microscopic characterization	Quality & Reliability	ACCEPT
29	Mingtai Li, Wenning Huang, Ziyan Guan, Li Zhang and Hongwen He	Optimization of Ultra-low Wire Loop to Improve Reliability of Wire Bond in Multi-die Vertical Package using FOW	Packaging Design & Modeling	ACCEPT
30	Fangzhou Chen, Baorui Wu and Jiahao Liu	In-situ Measurement and Characterization of Self-Healing Processes in Biaxially Oriented Polypropylene (BOPP) Metallized Film Capacitors	Quality & Reliability	ACCEPT
31	Zhaowei Jia, Chenhua Lu, Qiqiang Wang, Jian Wang, Hongchao Yang and Daquan Yu	Improvement of the Coplanarity of Electroplated Mixed Bumps under High Current Density	Packaging Materials & Processes	ACCEPT
32	Dao-Hang Li, Can-Pu Wang and Yun-Hui Mei	Improved Anand model considering the influence of sintering process on the packaging interconnection of power modules	Quality & Reliability	ACCEPT
33	Qinglei Sun, Yifan Yao, King-Ning Tu and Yingxia Liu	Investigation of the Bonding Mechanism of Geopolymer Adhesive with Alumina Ceramics for DUV LED Packaging	Interconnection Technologies	ACCEPT
34	Fei Su	Infrared photoelasticity and its applications in the stress evaluation of wafer/chip	Quality & Reliability	ACCEPT
35	Yu Ban	A 25Gb/s integrated MZM modulator and high bandwidth electrical driver with a packaged chipset in an optical module for high speed optical interconnects	Optoelectronics and New Display	ACCEPT
37	Yingxi Hu	Multiphysics-Coupled Reliability Prediction of Ball Grid Array (BGA) Devices: Failure Mechanisms and Lifetime Assessment Under Synergistic High-Frequency Power Cycling and High Power Dissipation	Quality & Reliability	ACCEPT
38	Qiaochu Guo, Yi Cui, Sijia Cao, Jinhua Zhou, Shuping Meng and Xuebin Wu	Study of a Failure of a Compact Ceramic No-Lead Package Due to Tinning Induced Thermal Shock and Its Design Improvement	Quality & Reliability	ACCEPT
39	Jin Yang, Lei Han, Jian Zhu, Junzhi Zhang, Min Huang and Hongze Zhang	Application of system in package technology in bus data acquisition and processing	Advanced Packaging	ACCEPT
41	Lei Zhu, Ke Xu, Eric Lau, Wen Li, Younan Hua, Yanfei Zhao and Xiaomin Li	Failure Analysis of BGA Dewetting by X-Ray Photoelectron Spectroscopy	Quality & Reliability	ACCEPT

Paper ID	Authors	Title	Track	Decision
42	Yifan Peng, Jianxin Qiao, Longqiu Li and Cui Jing	Thermal Resistance Network Modeling Method Based on Chip Layered Structure	Quality & Reliability	ACCEPT
44	Hao Luo, Hu He, Zhoufang Liao and Chaowei Jiang	Improving Electroplating Uniformity on 12-inch Wafers through Coordinated Electric Field Management and Mass Transport Optimization	Advanced Manufacturing	ACCEPT
45	Younan Hua	PDMS Fingerprint of TOF-SIMS Techniques and Applications in Failure Analysis	Quality & Reliability	ACCEPT
46	Peixuan Li, Zishan Xiong, Rui Kang and Yingxia Liu	Study on Electromigration-Induced Degradation of Copper Interconnects under Combined Temperature-Humidity Stress	Quality & Reliability	ACCEPT
47	Guangmi Li, Song Xue, Shaoyi Liu, Jinyang Mu, Qiongfang Zhang, Dongchao Diwu and Congsi Wang	Investigation on the influence of wire thermal ultrasonic bonding process on the growth of intermetallic compounds by molecular dynamics simulation	Packaging Design & Modeling	ACCEPT
48	Paul Wang	Press-fit Technology Roadmap--Interconnect and Assembly Challenges of 2024 and 10 years Beyond	Interconnection Technologies	ACCEPT
50	Junwei Chen, Tao Luo, Wei Chen, Guoqi Zhang and Jiajie Fan	Evaluating the high temperature reliability of glass encapsulant packaged SiC Schottky diodes with high-temperature step stress aging test	Power Electronics	ACCEPT
52	Chuan-Shun Li, Wen-Yu Teng and Liang-Yih Hung	Mechanical Properties analysis of Indium-Silver Alloys Thermal Interface Materials for FCBGA Reliability	Packaging Materials & Processes	ACCEPT
53	Zhang Yingjie, Wang Zihan, Liu Yue, Wan Xiaoling, Yang Xiaofeng and Chen Bin	Research on the Development of a Multi - Stress Coupled Thermal Resistance Evaluation Fixture for AI Computing Power Chips and the In - Situ Testing Method with Thickness	Quality & Reliability	ACCEPT
54	Zhang Yingjie, Gan Jisong, Mo Fuyao, Zhu Gang and Chen Chengcheng	Corrosion Mechanisms and Protection Strategies for Tin and its Alloys in Electronic Components: A Review	Quality & Reliability	ACCEPT
55	Qiang Chen, Guosong Zhang, Chengming Cui, Minyan Wu and Yonghua Zhou	Thin Package Strength and Prediction Study	Quality & Reliability	ACCEPT
56	Ming-Han Zhuang, Hei-Chi Yang and Ho-Chuan Lin	Signal integrity optimization of high-speed SerDes signals in flip-chip package substrates using a parametric 3D modeling program	Packaging Design & Modeling	ACCEPT
59	Shiwei Zhang, Yiming Li, Tong Sun, Fangqiong Luo, Yang Wang, Yincai Zhao and Jingjing Bai	A novel vapor chamber with inverse opal mesh wick for submillimeter-scale microelectronic thermal management	Power Electronics	ACCEPT
60	Min Wei, Haibin Liu, Lezhi Ye and Yanfeng Wei	Profile Optimization and Numerical Analysis of a Novel Asymmetric Rotor for Claw-type Dry Vacuum Pumps in Semiconductor Manufacturing	Advanced Manufacturing	ACCEPT

Paper ID	Authors	Title	Track	Decision
61	Shuye Zhang, Guoli Sun, Binhao Qin, Haiyan Wang, Laifa Ding, Qingyang Qiu and Yupeng Zhang	A Novel Multiscale Homogenization Strategy for Large-Scale Glass Substrates	Quality & Reliability	ACCEPT
62	Ruijie Liu, Haifa Qiu and Yun Mou	A Novel Packaging Optimization Digital Design Framework of Power Modules Using Data-Driven Modeling and Intelligent Optimization Techniques	Packaging Design & Modeling	ACCEPT
63	Jialin Zhang, Hangqian Wang, Shuye Zhang, Xialei Lv, Jinhui Li, Guoping Zhang and Rong Sun	Synthesis of Fluorinated Alkali-Soluble Photosensitive Resin and Study on the Application in Solder Resist	Packaging Materials & Processes	ACCEPT
64	Xiaodan Luo, Younan Hua and Yifeng Li	Precision Dicing Sample Preparation Technique and Application in Failure Analysis of Wafer Fabrication	Quality & Reliability	ACCEPT
66	Weishan Lv, Jiaxin Liu, Liu Yang, Yuebin Zhou, Daming Wang and Cai Chen	Time dependent behavior of sintering mechanism and mechanical failure response of nano-silver under pressure-assisted bonding	Packaging Materials & Processes	ACCEPT
67	Yiliang Gao, Yawen Liu, Lijia Liu and Chunhong Zhang	Design and synthesis of low K epoxy resin and curing agent	Packaging Materials & Processes	ACCEPT
68	Tang Rui, Zhang Jinwen, Du Jianyu and Wang Wei	NUMERICAL OPTIMIZATION OF INLET DESIGNS FOR DIAMOND MICROCHANNEL HEAT SINKS	Advanced Packaging	ACCEPT
70	Yongjie Ding, Qing Wang, Yang Peng and Mingxiang Chen	Direct plated copper diamond substrates and their heat dissipation applications for laser diodes	Packaging Materials & Processes	ACCEPT
71	Hoogwan Lee, Dongmyeong Lee, Junyoung Choi, Suin Jang and Sarah Eunkyung Kim	Effect of CH4 Plasma Pretreatment on Cu-to-Cu Bonding Applications	Interconnection Technologies	ACCEPT
72	Jun Han, Xiaoyu Zhou, Yunpeng Li, Jie Jiao, Fan Wu, Ziyang Wei, Liangchun Han, Zhuoran Zhang and Junhua Tang	Research on Reliability Risk of Flip Chip Copper Pillar Bumping Design	Quality & Reliability	ACCEPT
73	Xinyu Huang, Fangting Chen and Jing Chen	Cryogenic Reliability and Electrical Performance of TVS Diodes	Quality & Reliability	ACCEPT
74	Yuanhang Chen, Feng Zhang, Liuyin Li, Shuhui Yu and Suibin Luo	Low dielectric epoxy composites cured with synthesized binaphthyl-based active ester	Packaging Materials & Processes	ACCEPT
75	Taolun Yang and Hu He	A Hybrid Approach Integrating Gradient Structural Design and Multi-Scale Modeling for Thermal and Mechanical Optimization in High-Power Electronics Packaging	Packaging Materials & Processes	ACCEPT
76	Tao He, Bin Xie, Zhoulong Xu, Dong Ye, Wei Chen, Zhouping Yin and Hao Wu	Revealing the influence of key parameters on wafer-to-wafer hybrid bonding dynamics through fluidstructure coupled simulation	Packaging Design & Modeling	ACCEPT

Paper ID	Authors	Title	Track	Decision
77	Qiang Wei, Weidong Liu, Pengkai Wang, Jiachen Wang, Xiaojian Ma and Huan Yang	Study on Thermal Stress Distribution Characteristics and Crack Failure Mechanisms of Die	Packaging Design & Modeling	accept?
78	Huiquan Cao, Zhou Yang, Jiajie Kang, Wei Wang and Chi Zhang	Multi-Layer Microchannel Cooling for Large-Area High-Power Electronics	Emerging Technologies	ACCEPT
79	Chao Jin, Geng Li, Baorui Wang, Ziyi Wang and Yanhong Tian	AdaBoost ensemble learning algorithm for precision manufacturing of aerosol jet printing	Emerging Technologies	ACCEPT
80	Junyoung Choi, Suin Jang, Dongmyeong Lee, Hoogwan Lee and Sarah Eunkyung Kim	Study on the deposition and low-temperature bonding of PVD SiCN thin film	Packaging Materials & Processes	ACCEPT
81	Suin Jang, Junyoung Choi, Dongmyeong Lee, Hoogwan Lee and Sarah Eunkyung Kim	Evaluation of Fly Cutting for Planarization in Cu/Polymer Hybrid Bonding and Its Effects on Polymer Materials and Processing Conditions	Advanced Packaging	ACCEPT
82	Yuxuan Fan, Quanlu Zhao, Wenwen Zhang, Yunyan Zhou and Qidong Wang	Design and Verification of Fan-Out on Substrate Package Interconnects Based on UCIe	Interconnection Technologies	ACCEPT
84	Dongqing Fang, Zhensong Li, Bingjie Li, Wenbo Mu and Chenghao Yuan	Design of Chiplet-based Domain Specific Architecture with Scalable Mac Array	Packaging Design & Modeling	accept?
85	Hang Liang, Xincheng Zhang, Yu Zhao, Haozhong Wang, Bingxu Ma, Xing Fu and Xiaofeng Yang	Thermal Interface Resistance Measurement and Degradation Mechanisms of Ti/X (X: Si, Cu, Au) Interfaces	Quality & Reliability	ACCEPT
87	Shuye Zhang, Jinhong Liu, Shujian Feng, Danting Li, Yansheng Wang, Qiangqiang Nie, Junfu Liu and Peng He	A Novel Insight into the Delamination of Thin-Film Layer on Microwave Dielectric Ceramic: The Role of Cleaning Agents	Advanced Packaging	ACCEPT
90	Huiling Feng, Hui Liang, Yiming Luo, Gang Li, Pengli Zhu, Binbin Zhou and Rong Sun	Interface aging mechanism of SiO2/EP in underfill investigated by in-situ Raman spectroscopy	Packaging Materials & Processes	ACCEPT
91	Yanlin Ma, Jie Li and Zhiyong Zhong	Cold Sintering of Co2Z Ferrite at 300 °C for High-Frequency Packaging Antenna Applications	Packaging Materials & Processes	ACCEPT
92	Yang Xiao, Jie Li and Yingli Liu	Modulation mechanisms of dodecahedral site vacancy defects on the magnetic and dielectric properties of YIG microwave ferrites	Packaging Materials & Processes	ACCEPT
93	Gang Dong and Daihang Liu	Fast Thermal Model of TTSV Based on Bounded Neural Networks	Packaging Design & Modeling	ACCEPT
94	Qingxi Mo, Hanwen Cui, Yanze Gao, Yuzheng Guo, Sheng Liu and Zhaofu Zhang	Cross-Scale Thermodynamic Simulation of RDL Using Hybrid Machine Learning and Finite Element Modeling	Advanced Manufacturing	ACCEPT

Paper ID	Authors	Title	Track	Decision
95	Qilong Guan, Kai Li, Shuo Kong, Guanghui Cui and Chunjin Hang	Effect of electron irradiation on the mechanical properties of SnPb eutectic solder joints: A combined experimental and first-principles study	Quality & Reliability	ACCEPT
96	Yujie Li, Shuo Yang and Jianzhu Li	Enhancing Bonding Strength in Heterogeneous Interfaces: The Role of Surface Structuring in Al/PI Systems	Packaging Materials & Processes	ACCEPT
98	Bin Xie, Yuanhui Guo, Yun Chen, Maoxiang Hou and Xin Chen	Self-powered humidity sensor based on a polyamide/laser-induced-graphene flexible composite film	MEMS, Sensors and IoT	ACCEPT
101	Jinxu Liu, Jihua Zhang and Zhen Fang	Computation of Parasitic Inductance in Through-Glass Vias: Coupled Analysis of Skin Effect and Morphology	Packaging Design & Modeling	ACCEPT
102	Xinixn Li, Shouwei Li and Caisheng Zhou	Research on the effect of temperature aging on microstructure evolution and mechanical behavior of lead and lead-free solder joints	Quality & Reliability	ACCEPT
103	Bihong Zhan and Sheng Liu	Experimental analysis of magnetically coupled resonant wireless energy transfer system	Quality & Reliability	ACCEPT
108	Hongjin Zhang, Tianyang Xu, Jiuzhou Zhao, Yang Peng and Mingxiang Chen	Heat-conducting Phosphor-in-Glass Film for High-brightness Laser Lighting	Optoelectronics and New Display	ACCEPT
109	Xuehan Li, Kun Ma, Yameng Sun, Xun Liu, Yifan Song, Anning Chen, Yang Zhou, Sheng Liu, Ziyi Xia and Liming Han	Thermo-Mechanical Coupling-Based Optimization and Reliability Assessment of Cu Clip Packaging Structures	Power Electronics	ACCEPT
110	Zhipeng Shen, Yanhao Chen, Yijun Shi, Lijuan Wu, Liang He, Xinghuan Chen, Yuan Chen, Dongsheng Zhao, Huangtao Zeng and [illegible]	The Impact of Load Dump Stress on E-Mode P-GaN HEMTs Under Half-On Gate Bias Condition	Quality & Reliability	ACCEPT
111	Yuguo Kou, Yanpeng Gong and Fei Qin	Phase field modeling of fracture behavior in sintered silver	Packaging Design & Modeling	ACCEPT
113	Zikang Yu, Yang Peng and Mingxiang Chen	Heat dissipation enhancement of phosphor converter in white laser diode by diamond substrate	Optoelectronics and New Display	ACCEPT
114	Fenny Liu, Renata Hsiao, Liang-Yih Hung, Andrew Kang and Yu Po Wang	PFAS Methodology Study for Assembly Materials	Packaging Materials & Processes	ACCEPT
115	Nannan Li, Lijuan Wang, Xuewei Zhao, Jianmin Song, Qijun Lu, Chaoyang Xing and Yuxin Xu	Electrical Characteristics Simulation of Low-Resistivity Si-TSV Interposer for Inertial Navigation System Integration	MEMS, Sensors and IoT	ACCEPT
116	Xinyu Li, Fangting Chen, Xiaojing Fan, Mifeng Liu, Lei Ding, Yan Luo, Bin Sun and Kai Chen	High-Reliability Power Microsystem Integration Technology and Its Application to Multi-Channel High-Power Driver SiP	Packaging Design & Modeling	ACCEPT

Paper ID	Authors	Title	Track	Decision
117	Nannan Li, Xuewei Zhao, Lijuan Wang, Jianmin Song, Chaoyang Xing, Yuxin Xu, Yang Liu and Yuxiong Xue	Thermal Stress Characterization and Analysis of Inertial Sensor/System Integration based on Low-Resistivity Si-TSV	MEMS, Sensors and IoT	ACCEPT
118	Yida Lei, Jie Li and Wu Zhang	High-Performance Sr-Mn Co-Substituted BaM Ferrite for Microwave Applications	Packaging Materials & Processes	ACCEPT
119	Kaihua Lou, Yongwang Zhou, Yang An, Qihao Liu, Zhaogui Zeng and Ji Zhong	A Review of High Bandwidth Memory Technology	Advanced Manufacturing	accept?
120	Huangtao Zeng, Yanhao Chen, Yijun Shi, Zhiyuan He, Guoguang Lu, Liang He, Yuan Chen, Xinghuan Chen, Xianzhong Zhou and Zhipeng Shen	Degradation Phenomena in Monolithically Integrated GaN Chips Under Load Dump Stress with Floating Gate Conditions	Quality & Reliability	ACCEPT
121	Zhen Fang, Jihua Zhang, Jinxu Liu, Shuqi Li, Donbin Wang and Hongwei Chen	Antenna-in-Package Design with TGVs and LTCC Heterogeneous Integration	RF Electronic Packaging	ACCEPT
122	Haitao Ma, Jing Xing and Jie Zhang	Comparison of diffusion barrier performance between smooth and cellular Ni-P layer	Packaging Materials & Processes	ACCEPT
123	Jun Huang, Jianquan Chen, Enliang Li, Jianxiong Liu, Yangbin Fang, Xiaoling Lin, Xiaofeng Yang, Yu Zhang, Chao Li and Chengqiang Cui	Formation of Glass Microcrack Induced by Non-uniform Copper Grain Growth in Through Glass Via During Reflow Soldering	Advanced Manufacturing	ACCEPT
124	Shaofeng Wang, Hongxu Wu, Shangyang Shi, Wei Wang and Chi Zhang	Thermal Fatigue Reliability of Silicon-Based Thermal Management Devices	Quality & Reliability	ACCEPT
125	Norimitsu Ichikawa	Induced voltage generated in conductive plastic box when a charged object near the box is grounded	Quality & Reliability	ACCEPT
126	Haoyang Xiao, Chuanbin Men, Yanchun Xiong, Guanqiang Song, Weijie Zhang, Yuhong Li and Jing Jiang	Enhancing signal transmission rate in photon-counting computed tomography detectors	Packaging Materials & Processes	ACCEPT
127	Liu Yang and Jinxiu Gong	Simulation analysis of clip bonding package	Packaging Design & Modeling	accept?
128	Dingkun Tian, Shulin Lei, Yadong Xu, Yougen Hu, Guoping Zhang and Rong Sun	Thermally Detachable Expandable Microspheres/Silver Composite Films for PCB-Level Conformal EMI Shielding	Packaging Materials & Processes	ACCEPT
129	Zeyu Zheng, Yang Liu, Hebin Zhang, Jialin Wen, Junhao Liu, Haofeng Ouyang, Yan-Jun Wan and Rong Sun	Electrically Insulating Yet Electromagnetic Interference Shielding Epoxy Composite for Advanced Electronics packaging	Packaging Materials & Processes	ACCEPT
130	Dongmyeong Lee, Junyoung Choi, Suin Jang, Hoogwan Lee, Keiyu Komamura and Sarah Eunkyung Kim	Effect of Palladium Passivation via Electroplating and Electroless Plating on Low-Temperature Cu-to-Cu Bonding	Interconnection Technologies	accept?

Paper ID	Authors	Title	Track	Decision
131	Junjie Zhang, Wenqi Lv, Chen Yun, Maoxiang Hou and Chuhao Cai	Additive-assisted laser-induced wet etching for fabricating high-perpendicularity through glass vias	Interconnection Technologies	ACCEPT
132	Ting Xin, Haofeng Ouyang, Zeyu Zheng, Gang Li, Rong Sun and Pengli Zhu	Synthesis of Chemically Modified Lignin-Epoxy Composites with Enhanced Interfacial Adhesion for Underfill	Packaging Materials & Processes	ACCEPT
133	Min Kang, Heran Zhao, Zuoya Zheng, Hongjun Li, Chenyang Zhou and Lingfeng Chao	Research on the thermal environment adaptability of perovskite solar cell micro-integrated packaging devices	Quality & Reliability	ACCEPT
134	Deguang Yang, Gang Dong and Changle Zhi	An Artificial Intelligence Method for Efficient Design of 3D Power Distribution Network	Packaging Design & Modeling	ACCEPT
135	Zifen Xu, Dongyan Ding, Chaoyuan Mary Liu and Cheekiang Yew	Heat dissipation performance of QFN package with concentric circle Cu heat sink	Packaging Design & Modeling	ACCEPT
136	Chang Wang, Bin Xie, Zhoulong Xu, Dong Ye, Wei Chen, Zhouping Yin and Hao Wu	Simulation analysis of stress optimization in large-area ultra-thin chip peeling	Packaging Design & Modeling	ACCEPT
137	Jiayu Li and Yang Peng	Near-junction heat dissipation of high-power chips by copper-diamond based heat sink	Packaging Materials & Processes	ACCEPT
139	Zhuolin Tang, Canyu Liu and Changqing Liu	Investigation on the reliability of TSV embedded micro pin-fin channel cooling in 3D integrated chip	Quality & Reliability	ACCEPT
143	Shichen Xie, Fuxin Du, Zishan Xiong, K.N. Tu and Yingxia Liu	Nanocrystalline Cu for rapid Cu-Cu bonding without post-annealing process	Interconnection Technologies	ACCEPT
144	Keke Zhang, Qianqian Hu, Shuhan Shi and Weikang Zhao	Research on the Interconnection reliability of Substrate-like printed circuit board for AI Servers	Interconnection Technologies	accept?
145	Yanfei Zhao, Zhiyuan Wang, Tuanqiao Hu, Lei Zhu and Xiaomin Li	Failure Analysis of Surface Contamination on Pellicle Film used in EUV Lithography	Quality & Reliability	ACCEPT
146	Jui Ang Tan, Chee Chuan Tan, Alvin Kok Wah Leong, Soo Chun Khor and Khian Chee Chua	RAC Process characterization in SMT PCBA	Advanced Manufacturing	ACCEPT
147	Hanmin Peng, Yuwen Su, Meirong Li and Yangyang Yan	Fabrication of TSVs with Polyimide Liner in SOI Wafers for Micromirror Array Applications	Advanced Packaging	ACCEPT
148	Xiaojiu Tang, Kai Li, Fengchu Li, Shengli Li, Qilong Guan, Dan Yu, Ying Ding, Xiuli Wang and Chunjin Hang	Multifunctional Fe_3O_4@$Ti_3C_2T_x$/EP composite with accordion-like structure in electronic packaging applications	Packaging Materials & Processes	ACCEPT

Paper ID	Authors	Title	Track	Decision
149	Jinxiu Gong and Liu Yang	Research on ceramic cutting technology and module installation risk	Packaging Materials & Processes	ACCEPT
150	Su Dezhi, Wang Hongkun, Wang Cen, Fuxin Wang and Xinglong Zhan	A Comparative Simulation Analysis of Thermal-Mechanical Performance Between Two Plastic Packaging Architectures for System-in-Package (SiP) Modules	Packaging Design & Modeling	accept?
151	Yongli Shen, Huixia Cao, Jingtian Li, Xi Lu, Yong Wang, Xiehuai Luo, Yadong Xu, Yougen Hu and Rong Sun	UV-Thermal Dual-Curing Anisotropic Conductive Paste for Low-Temperature RFID Tag Packaging	Packaging Materials & Processes	ACCEPT
152	Fengyi Wang and Hongtao Chen	Application of Selective Electrodeposition of Copper Arrays Based on Bicontinuous Microemulsion in Power Device Packaging	Packaging Materials & Processes	ACCEPT
153	Hao Chen, Xin Zou, Zhirui Xu and Mingxiang Chen	Preparation and Process Optimization of High-Temperature Resistant Hermetic Multilayer Ceramic Substrate	Packaging Materials & Processes	ACCEPT
154	Fupeng Huo, Chuantong Chen, Sangmin Lee, Dongjin Kim, Aiji Suetake, Kazutaka Takeshita, Yoshiji Yamaguchi, Yashima Momose and Katsuaki Suganuma	Anti-oxidation sintering of Ag-10Cu composite paste on DBC substrate in air atmosphere	Power Electronics	ACCEPT
155	Chuanyu Wu, Jie Liu and Jinhui Li	Toughening and Performance Enhancement of Epoxy Acrylate-Based Solder Resist Using Polyurethane Acrylate for Advanced Packaging	Packaging Materials & Processes	ACCEPT
156	Shaocheng Wu, Fei Lu, Jiazhe Zhang, Rongbin Xu, Yuhang Dou and Daquan Yu	The coupled BAW/SAW ScAlN resonator with high frequency and high electromechanical coupling coefficient.	MEMS, Sensors and IoT	ACCEPT
157	Hui Xiao, Xuanlong Chen, Hui Tang and Tao Lu	Investigation of Interconnection Faults in Plastic SiP Modules: Failure Mechanisms and Reliability Insights	Quality & Reliability	ACCEPT
159	Xin Zou, Qing Wang, Hao Chen, Zhirui Xu and Mingxiang Chen	DPC Ceramic Substrate Plating Internal Stress and Warpage Analysis	Quality & Reliability	ACCEPT
161	Peng Fu and Zhidong Xia	Laser-Irradiated Carbon Nanotube-based Flexible Electrodes for Enhanced Performance in Wearable Electronic Sensors	Emerging Technologies	ACCEPT
164	Xiuming Liu, Jianshu Liu, Dongliang Zhang and Sheng Liu	Revealing the toughening mechanisms in graphene/AlN packaging composites with hierarchical nacre-like structures	Packaging Materials & Processes	ACCEPT
165	Ziting Guo and Kangjie Zhang	Adaptive Dual-Threshold Edge Detection on FPGA Using Enhanced Sobel Operator	Advanced Manufacturing	ACCEPT
166	Kangjie Zhang and Ziting Guo	Research on Improved Active Disturbance Rejection Control Strategy for Advanced Packaging Motion Platforms	Advanced Manufacturing	ACCEPT

Paper ID	Authors	Title	Track	Decision
167	Xing Xu, Dan Li and Gaiqing Chen	Microstructure and bonding ratio of microstrip plates ultrasonically soldered with Ni-foam/Sn-Pb composite solder	Quality & Reliability	ACCEPT
169	Xiaojian Liu, Fang Yu, Ying Ding and Yuqing Zhang	Finite element simulation study of heat sink structure for integrated ceramic substrates	Packaging Design & Modeling	accept?
171	Hao Huang, Xin Li, Defeng Liu, Xin He, Haoyang Pang, Tao Jin, Xiaowei Niu, Yanbo Cai and Min Yu	Boron diffusion at high temperature in ion-implanted 4H-SiC	Advanced Manufacturing	ACCEPT
172	Zhirui Xu, Qing Wang, Xin Zou and Mingxiang Chen	Through-ceramic-via filling by copper electrodeposition using single additive amine-terminated polyethe	Interconnection Technologies	ACCEPT
174	Jing Zhang, Bojie Lou, Yongwang Zhou, Yang An, Qihao Liu, Zhaogui Zeng and Ji Zhong	Read disturb mechanisms and solutions in 3D NAND Flash	Quality & Reliability	ACCEPT
176	Loon Wooi Fook	Effect of UV Laser Cut Parameters on Thin FR4 PCB ENIG Pad Oxidation/Discoloration	Advanced Packaging	ACCEPT
178	Chien-Hung Yang, Fa-Chuan Chen, Wei-Tsung Tang, Chien-Min Lin, Che-Kuan Chu, Yu-Hsing Lin and Yin-Fa Chen	High-Precision X-ray Inspection of Flip Chip Packaging Leveraging Deep Learning and Instance Segmentation for Manufacturing Process Optimization	Quality & Reliability	ACCEPT
179	Rui Yang, Guangbin Dou and Chunyan Yin	Antenna-in-Package Design Based on Fan-Out Wafer-Level Packaging	RF Electronic Packaging	ACCEPT
181	Chen Zhao, Zhidong Xia and Peng Fu	A CNT-Graphene/PDMS Composite Conductive Film Electrode via Spray-Coating for Flexible Capacitive Sensors	MEMS, Sensors and IoT	ACCEPT
182	Pan Ren, Cong Liu, Yaya Liang, Shaohui Liu and Pingan Du	A Finite Element-Based Method for Cohesive Zone Model Parameter Extraction in 2.5D Packaging Interfaces	Quality & Reliability	ACCEPT
183	Jianquan Chen, Hongyu Tang, Zhangsen Cen, Yi Xie and Daoguo Yang	Optical Design of Micro-LED Arrays for Photoplethysmography Sensor	Optoelectronics and New Display	ACCEPT
184	Junhao Liu, Xuecheng Yu, Haofeng Ouyang, Zeyu Zheng, Yang Liu, Rong Sun, Gang Li and Pengli Zhu	The application of covalent organic framework (COF)-modified silica fillers in Dam fills for electronic packaging	Packaging Materials & Processes	ACCEPT
185	Jianyu Tang, Zehui Lan, Zihao Liu, Rong Sun, Gang Li, Ruoyu Zhang and Pengli Zhu	Effect of Silica Filler Content on Fatigue Performance of Underfill	Quality & Reliability	ACCEPT
186	Xi Liu, Huan Yang and Wenbo Wang	Thermal Resistance Optimization in High-Power AI Chip Package: Multi-Structure FC package Comparison, Heat Spreader Design, and Indium metal TIM Innovation	Packaging Design & Modeling	ACCEPT

Paper ID	Authors	Title	Track	Decision
188	Shu Yang, Yang Wang, Jingjing Bai, Caiman Yan, Yiming Li, Tong Sun, Shiwei Zhang and Fangqiong Luo	A hierarchical copper gradient mesh surface for enhancing thin film boiling heat transfer performance	Power Electronics	ACCEPT
189	Kaidong Huang, Lianqiao Yang, Ming Li and Yifan Guo	Signal integrity analysis of 2.5D package with silicon bridge	Packaging Design & Modeling	accept?
191	Ren-Kai Zhang, Li-Yin Gao, Hai-Tao Sun and Zhi-Quan Liu	Optimizing Through-Silicon Via (TSV) Filling: Effects of Copper Ion Concentration and Additive Molecular Weight in Stepwise Direct Current Electrodeposition	Packaging Materials & Processes	ACCEPT
192	Zhuohuan Wu, Jiaqi Liu and Yanhong Tian	Ultra-sensitive Flexible Temperature Sensor Based on Polyionic Elastomer with a Wide Detection Range	MEMS, Sensors and IoT	ACCEPT
193	Hsinlong Chen, Kai-Cheng Wang, Fa-Chuan Chen, Bo-Kuan Yeh, Yu-Hsing Lin and Yin-Fa Chen	Investigation of Bump Seed Layer Delamination in FCCSP Packages: Effects of Polyimide Geometry and Seed Layer Thickness on Adhesion Properties	Packaging Materials & Processes	ACCEPT
194	Bingchen Li, Weicheng Wu, Chengxin Wang and Yuhua Huang	Investigation of the Anti-Hall-Petch law on the Material Removal Behavior of Silicon Carbide	Packaging Materials & Processes	accept?
195	Yameng Sun, Liming Han, Zhulai He, Aning Chen, Kun Ma, Xun Liu, Yifan Song, Xuehan Li, Xiao Zhang, Yang Zhou and Sheng Liu	Impact of Common-Emitter Parasitic Inductance on the Turn-on Characteristics of IGBT	Power Electronics	ACCEPT
196	Kun Ma, Yameng Sun, Xun Liu, Yifan Song, Xuehan Li, Xiao Zhang, Anning Chen, Yang Zhou and Sheng Liu	Thermal Performance Optimization of Pin-Fin Structures in Electric Vehicle Power Modules via Response Surface Methodology	Packaging Design & Modeling	ACCEPT
197	Jingwen Zang, Pengrong Lin, Linfeng Chen, Yiming Ge, Xiaochen Xie and Shimeng Xu	Study of Moisture Penetration in Flip-chip Circuit with Organic Substrate by Deuterium Oxide (D2O) Isotope Tracing Technique.	Advanced Packaging	ACCEPT
198	Anning Chen, Tongtong Zi, Xinglin Zhou, Yameng Sun, Kun Ma, Xun Liu, Yifan Song, Xuehan Li, Xiao Zhang, Yang Zhou and Sheng Liu	Bonding-Wire Topology Reconstruction for Turn-on Voltage Bump Suppression and Switching Loss Optimization in High-Power IGBT Modules	Packaging Design & Modeling	ACCEPT
199	Ming Weng, Yu Zhang, Ranyuan Zhang, Hualei Lu, Yangbin Fang and Chengqiang Cui	Bonding Machine-Enabled Fine-Pitch Interconnects for Advanced Manufacturing	Advanced Manufacturing	ACCEPT
200	Zhe Xu, Yong Cao, Cheng Zhong, Tian Yu, Yang Feng, Haiyan Nan, Xi Wan, Xiaofeng Gu and Shuting Wang	A Temperature-modified Semi-empirical Quantitative Physical Model for Predicting Interfacial Contact Thermal Resistance for Chiplet Packaging	Packaging Materials & Processes	ACCEPT
201	Lingyun Liu, Zhijun Long and Jiangguo Zhang	Optimisation of return loss for 224G SerDes in FCBGA package	Packaging Design & Modeling	ACCEPT
202	Minghe Wang, Jinsong Fang, Weijian Zhang, Qixin Zhang, Yong Zhang and Yan Zhang	Study on the Heat Transfer Characteristics in Epoxy Composites with Bioinspired Fractal Skeletons	Packaging Design & Modeling	ACCEPT

Paper ID	Authors	Title	Track	Decision
203	Xiaowei Wang, Mengke Yang and Qiuxi Li	Bridging HALT-HASA Chamber Discrepancies: A Case Study on Verification of Screen application and optimization	Quality & Reliability	ACCEPT
204	Xun Liu, Kun Ma, Yameng Sun, Yifan Song, Xiao Zhang, Xuehan Li, Yang Zhou, Sheng Liu, Anning Chen, Zhulai He, Wei Huang and Ziyi Xia	Low pressure and high efficiency sintering of MOD modified Ag micro-flake pastes for power semiconductors die-attach	Packaging Materials & Processes	accept?
206	Jie Jia, Xiaoting Chen, Si Chen, Shengguo Lu, Xiaofeng Yang, Nan Hua, Guoguang Lu, Bin Zhou and Xiaodong Jian	A study of hotspots of the TSV-RDL interconnect structure	Quality & Reliability	ACCEPT
207	Cheng Zhong, Zesong Wang, Jinhao Liu, Liyin Gao, Zhiquan Liu and Rong Sun	Investigation of the Fracture Mechanism of Redistribution Layer Structures Using the Extended Finite Element Method	Packaging Design & Modeling	ACCEPT
209	Chaoping Wang, Xuefeng Wu, Zishan Xiong and Xiuchen Zhao	Electrodeposition Fabrication and Mechanical Properties Study of Ag–Zn Solid Solution Films	Packaging Materials & Processes	ACCEPT
210	Yifan Wang and Alfred Yeo	Design for Manufacturing in Wafer Level Fan-Out Packaging	Packaging Design & Modeling	ACCEPT
211	Qu Fang, Sun Jianjun, Wu Xiangwei, Yu Bin, Xie Yelei, Li Guangyao and Ouyang Keqing	Methods for Improving the Thermal Simulation Evaluation Accuracy of TIM1 with High-precision TTC Testing	Quality & Reliability	ACCEPT
212	Wanchun Tian	Research on the Failure Mechanism of TSV Interconnection Structure in RF Microsystem Modules under Temperature Stress	Quality & Reliability	ACCEPT
213	Jingtao Hong, Donglin Zhang, Jiaqi Feng, Qinghan Xie, Jian Zhang, Yuan Zhang, Shuquan Chen, Xiuchen Zhao, Gang Zhang and Yongjun Huo	A Study on Low-melting-point-alloy incorporated Epoxy-based Conductive Polymer Composites for Direct-write Printing Technology	Interconnection Technologies	ACCEPT
214	Fang Qu, Xiangwei Wu, Zhongxuan Tian, Bin Yu, Zongwei Wang, Qi Zhang, Kuo Zhang, Yelei Xie, Guangyao Li and Keqing	Thermal Performance Test Analysis and Reliability Verification of Graphene TIM1 Materials Based on FCBGA	Packaging Materials & Processes	ACCEPT
215	Sunjae Kim, Kangmin Seo, Suin Jang, Junyoung Choi, Dongmyeong Lee, Hoogwan Lee and Sarah Eunkyung Kim	Study on Cu Dishing in CMP Process and Its Impact on Hybrid Bonding by Pad Size	Advanced Packaging	ACCEPT
216	Bojun Chen, Gaowei Xu and Yang Huang	Three-dimension Integration for Superconducting Multi-chip Modules Based on Sidewall Vertical Interconnection of Silicon Interposer and/or Chips	MEMS, Sensors and IoT	ACCEPT
217	Jiaqi Song, Zhanpeng Tian, Cong Yuan, Yuan Zhang, Xin Tian, Tao Xu, Shuquan Chen, Xiuchen Zhao, Gang Zhang and Yongjun	Investigating Thick-Film Sintering Technology with Silicon Nitride Substrates for ASIC Interconnection	Interconnection Technologies	ACCEPT
218	Liu Li, Jie Zheng, Danni Cao, Zhen Liu, Wenhui Zhu and Liancheng Wang	Electromagnetic susceptibility Shielding Solution for SiP	Packaging Design & Modeling	ACCEPT

Paper ID	Authors	Title	Track	Decision
220	Siqi Zhang, Kelaiti Xiao and Yuechen Zhuang	Integrated Polymer Waveguide for High Density Wafer Level Optical Interconnection	MEMS, Sensors and IoT	ACCEPT
221	Jiayi Tang, Liang Cao, Guanghui Xu, Manqi Dong, Zepei Jiang, Yan Zeng, Anyang Xiong, Liang Wu and Ming Li	Predicting the dielectric properties of dielectric films in chip by machine learning methods	Emerging Technologies	ACCEPT
225	Zihan Jiang and Zheyao Wang	Fabrication of Conformal Polyimide Liners in TSVs with Various Dimensions by the Engineered Vacuum-Assisted Spin-Coating Technique	Interconnection Technologies	ACCEPT
226	Xiaofeng Yang, Xuebao Li, Zhang Li, Yongfan Zhan, Rui Jin, Peng Sun, Xinling Tang and Zhibin Zhao	Equivalent parasitic inductance modeling of SiC MOSFET power modules in dynamic current sharing	Packaging Design & Modeling	ACCEPT
227	Qiaobo Dai, Zhen Liu, Boyu Zheng, Lanying Xu and Wenjuan Guo	A Study on Mold Flow Characterization of Asymmetric Multi-Chip Stack Packages	Packaging Materials & Processes	ACCEPT
228	Xingshou Pang, Dazhen Wu and Harry Gan	Material and Modeling Study of Extremely Thin BGA(XFBGA) Warpage Caused by High Temperature Bake	Packaging Materials & Processes	ACCEPT
229	Hutao Shi, Kang Liang, Wei Shen and Zhenyang Lei	Warpage Simulation and Analysis of 8-Inch Wafers in the Damascene Process	Advanced Packaging	ACCEPT
230	Jingyi Zhao, Rui Ma, Meiying Su, Jun Li, Qidong Wang, Quanlu Zhao, Shanjun Ding, Zhidan Fang and Zhongyao Yu	Compare the effect of different algorithms in prediction of organic substrate warpage	Emerging Technologies	ACCEPT
231	Baizhao Tan, Xiaoru Liao, Kewei Pan and Zuoyan Han	Optimization of plating additives and process parameter for high aspect ratio TSV filling	Interconnection Technologies	accept?
233	Jiahui Wang, Jianfeng Fan, Xiaoliang Zeng, Shujun Cai and Yabiao Ma	Design and Research of High Thermal Conductivity, Yield-Tunable Silicone Thermal Interface Materials	Packaging Materials & Processes	ACCEPT
234	Hui Yuan, Mintao Zhang and Zhi Xu	Research on Reduced-Order Active Disturbance Rejection Controller for Permanent Magnet Synchronous Linear Motor	Advanced Manufacturing	ACCEPT
235	Jingyan Li, Xianli Xie, Penghui Guan, Huai Zheng and Qing Wang	Development of Integrated Microchannel Metal Substrates for Efficient LED Module Heat Dissipation	Packaging Materials & Processes	ACCEPT
236	Hongsheng Yang, Zhiqiang Chen, Ting Li, Xiaobo Hu, Anan Fang and Xiaojun Zhang	Development of a High Metal Ionization Physical Vapor Deposition System for High Aspect Ratio Through-Glass-Via Metallization	Emerging Technologies	ACCEPT
237	He Gao and Yilong Huang	Research on the Impact of Magnetron Sputtering Coating on Conformal Electromagnetic Shielding Performance	RF Electronic Packaging	ACCEPT

Paper ID	Authors	Title	Track	Decision
238	Chenyang Zhou, Heran Zhao, Min Kang, Liying Li, Hongjun Li and Shizhao Wang	Measurement and analytical AI modeling of mimosa action potentials	MEMS, Sensors and IoT	ACCEPT
239	Fangting Chen, Xinyu Huang, Ning Hua and Jing Chen	Impact of Gold Wire Bonding Geometries on RF Performance in Ka-Band Microstrip-to-Chip Interconnects: A Comprehensive EM Simulation Study	Interconnection Technologies	ACCEPT
240	Zhongdi Cui and Guangbin Dou	Structural Design and Wafer-level Processing of Quartz Crystal Oscillator Glass Package Based on Response Surface Optimization	Packaging Materials & Processes	ACCEPT
241	Xudong Luo, Dongdong Shao and Kunpeng Ding	Optimization Performance of Trench MOSFET Based on FOPLP	Advanced Packaging	ACCEPT
242	Lezhi Ye, Wen Meng and Congcong Yu	Study on the Thermo-Fluid Coupling Model of Hot Plates for Wafer Spin Coaters	Advanced Manufacturing	ACCEPT
243	Jingyan Li, Jinfeng Chen, Penghui Guan, Qing Wang, Xianli Xie, Huai Zheng and Sheng Liu	Design of Diamond Cooling Chip for Thermal Management of Chiplet-Based System	Packaging Design & Modeling	ACCEPT
244	Zhenzhao Zhang, Zhuofeng Liu, Wenjian Guo, Fenglin Wang, Yunpeng Guo and Mengzhu Lou	Machine learning accelerated the prediction of thermal conductivity in silicon nitride ceramics	Power Electronics	ACCEPT
245	Haichuan Shi, Jianxin Qiao, Bin Zhou, Dapeng Liu, Yifeng Ye, Yunkang Su and Longqiu Li	Research on Cu-Sn Interfacial Diffusion Behaviors of Ultrasonic-assisted Bonding by Molecular Dynamics Simulation	Advanced Packaging	ACCEPT
246	Shan Wang, Lijuan Zhang and Gonglin Liu	Research on Welding Soldering Characteristics Analysis and Methodology for large-size LCCC Packaged Devices	Quality & Reliability	ACCEPT
247	Manqi Dong, Liang Cao, Jiayi Tang, Zepei Jiang, Yan Zeng, Anyang Xiong, Liang Wu and Ming Li	Covalent grafting of passivation layer on Si(111) via aryl diazonium chemistry	Packaging Materials & Processes	ACCEPT
248	Zhangsen Cen, Daoguo Yang and Tianzuo Qin	Mitigation of Signal Integrity Issues in High-Speed Signals within System-in-Package Using Tabbed Routing Structure	Interconnection Technologies	ACCEPT
249	Shikai Sun, Lei Chen, Zhenlin Lu, Yongzheng Ren, Xuan Zhao and Lili Liu	Analysis of large-size planar plasticized microsystems warpage	Advanced Packaging	ACCEPT
251	Sichen Liu, Xiaochen Xie, Jian Zhang, Shiang Gao, Yuan Zhang, Shuquan Chen, Xiuchen Zhao, Gang Zhang and Yongjun Huo	Molecular Dynamics Simulation of the Mechanical Properties of Ag–Cu Supersaturated Solid Solution for High-Density Interconnect Applications	Interconnection Technologies	ACCEPT
252	Yifan Song, Yongfei Cheng, Tongtong Zi, Ziy Xia, Kun Ma, Yameng Sun, Xun Liu, Yang Zhou and Sheng Liu	Gate oxide reliability of planar-gate SiC MOSFET under repetitive avalanche stress	Quality & Reliability	ACCEPT

Paper ID	Authors	Title	Track	Decision
253	Peng Su, Qunxing Li and Jinhui Li	Synergistically Optimized Binary UV-Curable Resin for Solder Resist Ink	Packaging Materials & Processes	ACCEPT
254	Kun Feng, Jie Wu, Lili Jiang, Min Huang, Shixing Jia, Lei Wang and Yan Xia	Process Optimization of Laser Stealth Dicing for Piezoelectric Thin-Film Suspended Structures in MEMS Devices	MEMS, Sensors and IoT	ACCEPT
255	Ping He, Huijuan Liu, Zeyu Fan, Fangcheng Wang, Qiang Liu and Guoping Zhang	Laser-induced tungsten-based broad-spectrum materials for photonic debonding	Advanced Packaging	ACCEPT
256	Xingchao Mao, Yingxia Liu and Jingyu Qiao	Fabrication of high-density microbump arrays using SnIn nanoparticles	Packaging Materials & Processes	ACCEPT
258	Chang-Ming Cao, Ya-Fei Li, Tian-Yu Bao, Zhen Li, Su Ye, Yan Li, Wei Liu, Rong An and Tian-Ling Ren	Improving the plasma-activated bonding strength between polydimethylsiloxane and lithium niobate in the fabrication of microfluidic SAW devices	Emerging Technologies	ACCEPT
259	Wang Zihan, Gan Jisong, Wan Xiaoling, Liu Yue, Zhang Yingjie and Zhu Gang	Interfacial Compatibility Failure Mechanism and Mitigation Strategy: Physical Absorption-Induced Swelling in Immersion Cooling Fluids /SAC305 Flux Residue Interactions	Quality & Reliability	ACCEPT
260	Lezhi Ye, Xiang Wang and Lu Li	Flip Chip Temperature Control in Thermal Compression Bonding by Jet Impingement Cooling Method	Advanced Manufacturing	ACCEPT
261	Hao Tang, Min Qu, Hang Li, Yuan Zhou, Yuan Liu and Guoqi Zhang	Investigation of IMC Grain and Mechanical Properties in Sn-Ag-Cu-xBN Composite Solder	Packaging Materials & Processes	ACCEPT
262	Huidong Song, Miao Li and Xiaowei Sun	Assembly and Reliability Study of VNX Connector	Emerging Technologies	ACCEPT
264	Hongyan Tang, Houle Feng, Jingyong Song, Shiduan Fu and Haitao Fu	Analysis of impurities in plating solution of IC substrate	Quality & Reliability	ACCEPT
266	Danning Zhao, Leicong Zhang, Gang Li, Pengli Zhu and Rong Sun	Size-controllable Mesoporous Silica as Potential Fillers in Epoxy Composites for Electronic Packaging Applications	Packaging Materials & Processes	ACCEPT
269	Xin Liu, Hongjin Zhang, Zikang Yu, Jiuzhou Zhao, Yang Peng and Mingxiang Chen	PiGF@Al2O3 converter in a reflection mode for high-brightness laser-driven white lighting	Optoelectronics and New Display	ACCEPT
271	Linzheng Fu, Qiaobo Dai, Liu Li, Danni Cao, Jie Zheng, Liancheng Wang and Wenhui Zhu	Simulation study on thermal characteristics of flip chip packaging based on void effect of indium-based thermal interface materials	Packaging Design & Modeling	ACCEPT
272	Kangsen Peng, Yilong Huang, Yuan Huang and Cong Xi	Simulation and Experimental Validation on Low-Stress Bonding Process for Double-Layer Adhesive Systems	Interconnection Technologies	ACCEPT

Paper ID	Authors	Title	Track	Decision
273	Wenzhe Wang, Dongchang Ma, Guannan Yang, Quanzhen Li, Yu Zhang, Guanghan Huang and Chengqiang Cui	Effects of repeated laser scanning on the microstructure and resistivity of Cu nanoparticle circuit	Advanced Manufacturing	ACCEPT
274	Binbin Qi, Jingke Wang, Yinghuan Zhao, Zhiqiang Lin, Zhengxun Hu and Rong Sun	Performance Study of Temporary Bonding Materials in Backside Via Reveal Process	Packaging Materials & Processes	ACCEPT
275	Nan An, Yilong Huang, Dongsheng Yang, Jianxing Shi, Yuan Huang, Ruoheng Zhang and Chunyu Yu	Investigation of Process Parameters for Thermoultrasonic Flip Chip Bonding of 3D Chip Stacking	Advanced Packaging	ACCEPT
276	Xinyun Fan, Guangbin Dou, Chunyan Yin, Song Peng and Yanglong Zhu	Prediction of Fatigue Life Time and Optimization of PoP Solder Joints under Thermal Cycling Load	Quality & Reliability	ACCEPT
277	Lei Yang, Yi Xie and Huiping Tang	Cross-scale thermo-mechanical reliability study of cavity defects in copper sintered interconnect layer	Quality & Reliability	ACCEPT
278	Dan Zhu, Shiqi Zhang, Tian Fan, Junqi Wang, Xiao Liu, Wenjian Li and Zhen Ma	A Study on the Bonding Reliability of SiC Waveguide Loads for Satellite Communication	Quality & Reliability	ACCEPT
279	Chuanjia Wang, Ziniu Yu and Fulong Zhu	The Impact of Rough Interfaces and Tilt Angles on the Thermal Cycling Reliability of Through Glass Via	Advanced Manufacturing	ACCEPT
280	Shiping Chen, Dong Wang, Ming Yang, Kai Jiao, Jie Yan, Hongcheng Dou, Zhihang Feng, Yanfeng Fu and Xi Xiao	Enabling 3D Heterogeneous Integration of Silicon Photonics Chiplet Through UBM-Free Au-SnAg Bonding for 2Tb/s Optical Interconnects	Advanced Packaging	ACCEPT
281	Huiping Tang, Daoguo Yang, Lei Yang, Tianzuo Qin, Zhuangchao Zhan and Chunshu Wei	Study on Warpage Behavior of Antenna in Package (AIP) with Fan-Out Wafer Level Packaging Technology during EMC Curing Process	Advanced Packaging	ACCEPT
282	Sangmin Lee, Chuantong Chen, Fupeng Huo and Katsuaki Suganuma	Ag direct bonding for die-attach of SiC on Ti/Ag metalized Cu substrate after the pre-annealing	Power Electronics	ACCEPT
283	Rui Ma, Jingyi Zhao, Meiying Su, Chen Lijun, Jun Li, Qidong Wang and Liqiang Cao	Finite Element Analysis of Warpage in Large-Area Fan-Out Panel-Level Packaging	Packaging Design & Modeling	ACCEPT
284	Shujun Cai, Xiaoliang Zeng, Jiahui Wang and Yabiao Ma	Effect of Multi-Scale Aluminum Nitride Particles on Thermal Conductivity and Rheological Performance of Thermal Conductive Gel	Packaging Materials & Processes	ACCEPT
286	Yubing Gong and Qingli Mo	Wireless Interconnection Enabled TO-247 Packaging for SiC Power Devices: Parasitic Inductance Reduction and Thermal Management via Copper Plate Bonding	Packaging Design & Modeling	accept?
287	Feixiang Tang, Sheng Liu, Siyu He, Zhaoxu Zhou and Shun Xue	A Hyperelastic-Viscoplastic Model Based on Qian-Liu Model Incorporating Deep Learning	Packaging Materials & Processes	ACCEPT

Paper ID	Authors	Title	Track	Decision
288	Mamadou Sanogo, Thierry Kociniewski and Zoubir Khatir	Enhanced thermal imaging by thermoreflectance on trench IGBT using multi focus and illuminated images	Quality & Reliability	ACCEPT
290	Tian Guo, Haoran Ma and Hongwei Liang	Application of Induction-Heated Transient Liquid Phase Bonding in Three-Dimensional Packaging	Interconnection Technologies	ACCEPT
292	Yizhuo Dong, Rong Zeng and Wei Zhong	Effects of On-State Resistance Differences on The Static Temperature Equalization of Multi-chip Parallel SiC MOSFETs Power Modules	Packaging Design & Modeling	ACCEPT
293	Rui Zhang, Kunhao Tang, Jingyi Yuan, Fa Wu, Yahui Mao and Yiying Zhu	Atomic-scale insights into electromigration in Cu interconnects via a new molecular dynamics approach	Advanced Packaging	ACCEPT
294	Bolong Dong, Chuanqi Dong, Fan Yang, Tianyi Wang, Wenbo Zhu and Mingyu Li	Preparation of sea urchin-like silver microparticles with high sintering activity for power electronics packaging	Packaging Materials & Processes	ACCEPT
295	Qiwei Zhang, Cheng Zhong and Rong Sun	Optimization Algorithm Comparison for Material Selection Artificial Neural Networks	Packaging Design & Modeling	ACCEPT
296	Yanming Zhang, Wenhan Chang and Wenkai Luo	Identification and Stability Monitoring Method for Flip-Chip Bonding Process Parameters	Quality & Reliability	ACCEPT
297	Chaofan Qu, Jiexin Li, Zhaoshu Cai, Zeqiang Huang and Jiasheng Li	On-Chip Integration of Quantum Dot Pixel for Enhanced Light Extraction in Micro-LED Displays	Packaging Materials & Processes	ACCEPT
298	Yujia Liu, Kelaiti Xiao, Kai Zhang and Jin Zhang	Plasma Activation and Nitrogen Synergy for Oxidation-Resistant in Cu-Cu Hybrid Bonding Process	MEMS, Sensors and IoT	ACCEPT
299	Kaidi Chen, Gaoyu Dai, Luqiao Yin and Jianhua Zhang	Directional-emitting Micro-LED based on Kepler Microlens Array	Optoelectronics and New Display	ACCEPT
300	Dongshen Zhang, Binghao Xie, Haoze Zong, Yanglin Huang, Minbo Zhou and Xinping Zhang	A Novel Hybrid Cu-Cu_2O Submicro-nano-particle Paste with Enhanced Sinterability and Mechanical Property of Joints	Packaging Materials & Processes	ACCEPT
301	Yukun Zhao, Gaoyu Dai, Luqiao Yin and Jianhua Zhang	Micro-LED Projection System Based on Compact Lens Group and Resonant-cavity	Optoelectronics and New Display	ACCEPT
302	Xiaoqi Liang, Chunyan Yin and Guangbin Dou	Thermal Mechanical Simulation and Process Optimization of High Aspect Ratio TSV Based on Shape Analysis	Quality & Reliability	ACCEPT
303	Xinhui Meng, Zhu Yang, Hong Fan, Hao Fu, Luqiao Yin, Xiuzhen Lu and Jianhua Zhang	Electro-thermo-mechanical Coupling Simulations on Micro-LED Arrays with Multi-quantum well	Optoelectronics and New Display	ACCEPT

Paper ID	Authors	Title	Track	Decision
304	Fei Wang, Gaoyu Dai, Luqiao Yin and Jianhua Zhang	All-optical Neural Network Based on Micro-LED Display	Optoelectronics and New Display	accept?
306	Yifan Yao, Yuanxing Duan, Qinglei Sun, K. N. Tu and Yingxia Liu	Thermomigration of Gold in the Microbump	Quality & Reliability	ACCEPT
309	Jiaren Huo, Zeli Zhu and Weiwei Yan	Research on the interface cracks between glass and RDL based on glass substrates	Quality & Reliability	ACCEPT
313	Shizhen Li, Chenshan Gao, Qihang Zong, Yihong Zhu and Huaiyu Ye	Molecular Dynamics and Experimental Study on Nano-Copper Sintering with Carbon Nanotube Doping	Power Electronics	ACCEPT
314	Chenshan Gao, Qihang Zong, Xiaowei Zhang, Shizhen Li, Yuqi Wang, Lingen Wang, Guoqi Zhang and Huaiyu Ye	Study on Pressureless Sintering Mechanism and Reliability of Cu-Ag Composite Pastes	Power Electronics	ACCEPT
315	Chong Ma, Hongli Liu, Fei Qin and Yanwei Dai	Numerical model for predicting warpage of wafer with back-end-of-line layers: A comparison investigation	Quality & Reliability	ACCEPT
317	Chunsheng Zhu and Lichao Zhang	Enhancing Chip Security: A Novel 3D Secure Packaging Structure Against Invasive and Side-Channel Attacks	Advanced Packaging	ACCEPT
318	Dalong Chen, Laiti Xiake and Gaowei Xu	High-Throughput Flexible Electrode Packaging for Brain-Computer Interface Chips	MEMS, Sensors and IoT	ACCEPT
319	Yilong Huang	Enhancing Nano Ag Paste Sintering Performance and Reliability via Gas Pressure Sintering for Power Device Packaging	Packaging Materials & Processes	ACCEPT
320	Hechao Li, Kui Li, Yanwei Dai and Fei Qin	Modelling of ultrasonic bonding process and parameter effect on gold wire balloons	Quality & Reliability	ACCEPT
321	Zhuohao Zhang, Fei Qin, Kui Li, Daowei Wu, Yuting Zhang and Yanwei Dai	Effect of dual annealing process on stress-strain relations of through silicon vias-copper	Quality & Reliability	ACCEPT
322	Kaihong Hou, Zhengwei Fan, Yonggui Chen, Shufeng Zhang, Xin Fang, Yashun Wang and Xun Chen	Enhancing 3D IC Performance Through Multi-Objective Optimization of TSV-Based Designs	Quality & Reliability	ACCEPT
323	Chenglin Yang, Jun Li, Meiying Su, Fengze Hou and Lijiang Gao	Packaging Integration of 2.5D FPGA Based on Quadrant Distribution	Advanced Packaging	ACCEPT
324	Hechao Li, Yanwei Dai, Fei Qin and Kui Li	Numerical study on heat transfer behaviors in reflow soldering process	Quality & Reliability	ACCEPT

Paper ID	Authors	Title	Track	Decision
325	Zihao Liu, Jianyu Tang, Zehui Lan, Ruoyu Zhang, Rong Sun, Gang Li and Pengli Zhu	Effects of resin and Curing Agents on Residual Stress in Underfill Material and Wafer-level Warpage	Quality & Reliability	ACCEPT
326	Bo Sun, Kunzhao Li and Guikang Yang	Design of honeycomb microchannel radiator with tesla valve	Power Electronics	ACCEPT
327	Bo Sun, Guikang Yang and Kunzhao Li	Substrate Design Optimization for Mixed Media Packaging of RF Power Amplifiers	RF Electronic Packaging	ACCEPT
329	Shangru Han, Yanbo Tang, Wei Lin and Boping Wu	Study and application of probe factor calibration for measuring near-field electromagnetic interference	Quality & Reliability	ACCEPT
330	Zehui Lan, Zihao Liu, Jianyu Tang, Gang Li, Rong Sun, Ruoyu Zhang and Pengli Zhu	Effect of BCPs on Temperature-dependent Fracture Behaviors of Underfill: In-situ SEM-DIC Characterization	Quality & Reliability	ACCEPT
331	Zeyu Fan, Ping He, Chenghao Ma, Fangcheng Wang, Qiang Liu and Guoping Zhang	Research on Novel Laser Bonding Process for Advanced Packaging	Advanced Packaging	ACCEPT
333	Yubo Wang, Zhongxuan Tian, Xiangwei Wu, Qi Zhang, Chong Dong, Bin Yu, Guangyao Li and Keqing Ouyang	The Delamination Mechanism of Graphene TIM in FCBGA Packaging	Quality & Reliability	ACCEPT
334	Ce Zeng, Yanming Zhang, Yang Li, Yangyang Li, Xingqiao Ji, Qian Lu, Zhenduo Cui and Shengli Zhu	High-fidelity Thermomechanical Modeling of Substrates Using a Monoclinic Homogenization Method	Packaging Design & Modeling	ACCEPT
335	Yuhong Li, Jing Jiang, Guanqiang Song and Jianhui Liu	Reliability Research and Optimization of Fan-out Panel Level Packaging Chip Stacking	Advanced Packaging	ACCEPT
336	Guandong Liu	Smoothing Method for Deeply Reactive-Ion-Etched Sidewalls in an Optical Accelerometer	MEMS, Sensors and IoT	ACCEPT
337	Yujie Cheng, Lu Liu, Huacheng Fu, Xu He and Zhikuang Cai	A multi-scale constitutive model of porous sintered nano-silver	Interconnection Technologies	ACCEPT
339	Daoxiang Liu, Wenbin Chen, Kelaiti Xiao, Yu Zhang and Siqi Zhang	Chiplet In Metal	MEMS, Sensors and IoT	ACCEPT
340	Xiao Cui, Haotian Li, Yan Luo, Junwei Ma, Mifeng Liu, Lei Ding and Jiangbo Luo	Effects of coreless package substrate structure on signal integrity of chiplet interconnection	Interconnection Technologies	accept?
341	Lizhe Wang, Lili Yuan, Shiyong Yang and Haixia Yang	Photosensitive polyimides with adjustable taper angles	Packaging Materials & Processes	ACCEPT

Paper ID	Authors	Title	Track	Decision
342	Li Liu, Haojie Ma, Yuan Yuan, Xianglong Jia and Zhiwen Chen	Molecular Dynamics Study of the Complexation Mechanism of Functional Groups with Copper Formate	Emerging Technologies	ACCEPT
343	Haitao Fu, Wei Yang, Wei Guo, Senlin Yang and Hongyan Tang	High density interconnections copper pillars fabrication	Packaging Materials & Processes	ACCEPT
344	Li Liu, Yiwen Zou, Liting Nong, Xianglong Jia, Ming Li and Zhiwen Chen	Enhanced thermal and electrochemical stability of micron silver joints with MOD additives	Packaging Materials & Processes	ACCEPT
345	Zhihong Zhu, Junjie Ge and Wanli Li	Multi-scale simulation-driven design of multi-peak metal pastes with targeted thermodynamic properties	Interconnection Technologies	ACCEPT
346	Jie Shen, Zhiyin Gan and Chenhao Zhang	Simulation and Experimental Study on Heat Transfer Distribution of MPCVD Sample Platform Surface	Advanced Manufacturing	ACCEPT
347	Xuan Miao and Yufeng Li	Fabrication of Oxidation-Resistant Cu@glass Paste and Laser Patterning Technology for Si_3N_4 Thermal Management Substrate Metallization	Interconnection Technologies	ACCEPT
348	Yihong Zhu, Shizhen Li, Chenshan Gao, Qihang Zong and Huaiyu Ye	Molecular Dynamics Study on the Sintering Behavior and Mechanical Properties of Graphene-Doped Nano-Copper	Power Electronics	ACCEPT
349	Qiuxi Li, Mengke Yang and Xiaowei Wang	A Systematic Study on the Influence of CTE Matching and Mechanical Stress on the Lifetime of Solder Joints after Thermal Cycling Test	Quality & Reliability	ACCEPT
351	Yanze Gao, Hanwen Cui, Xinlu Teng, Runting Niu, Yikang Zhou, Kai Zheng, Yuzheng Guo, Sheng Liu and Zhaofu Zhang	Numerical Study of a Novel Stacked Structure Trench Capacitor in 2.5D Packaging	Advanced Manufacturing	ACCEPT
352	Qufeng Li, Guisheng Gan, Ruidong Yan, Junfeng Dou, Fangliang Li, Junxiong Zhu, Daochun Xie, Daquan Xia and Xiangtao Xu	Effect Of Double-Side Cooling Packaging on the Properties of Dual-Base-Island Packaging	Packaging Materials & Processes	ACCEPT
353	Xingyu Liu, Yanwei Dai, Kui Li and Fei Qin	Numerical investigation on delamination and warpage behaviors of three-dimensional multilayered packaging on packaging under thermal loading	Packaging Design & Modeling	ACCEPT
354	Xingyu Liu, Yanwei Dai, Kui Li and Fei Qin	Determination of fracture toughness and CZM parameters of interfaces for three-dimensional multilayered packaging on packaging	Quality & Reliability	ACCEPT
355	Sishuai Li, Yanpeng Gong, Fei Qin and Pei Chen	Virtual element method for thermomechanical problems in electronic packaging	Packaging Design & Modeling	ACCEPT
356	Minghui Yun, Junjie Zhang, Liang Tan, Hongbo Qin, Miao Cai, Yinyu Xiao, Jingjing Qu and Jiazhi Yang	Identification of Thermal Fatigue Failure within SiC-MOSFETs by Means of FDR Technology	Power Electronics	ACCEPT

Paper ID	Authors	Title	Track	Decision
357	Jianlu Xue, Hongbin Xia, Shun Tik Yeung, Rolf Brenner and Tobias Sprogies	Study on the Influence of Si Wafer Plasma Dicing Parameters on Trench Sidewall Quality	Packaging Materials & Processes	ACCEPT
358	Younan Hua and Xiaodan Luo	Precision Dicing Sample Preparation Technique and Application in Failure Analysis of Wafer Fabrication	Quality & Reliability	ACCEPT
359	Anan Fang, Ting Li, Hongsheng Yang, Zhiqiang Chen, Xiaobo Hu and Xiaojun Zhang	Research on mitigating substrate warpage in panel-level packaging under vacuum heating conditions	Advanced Manufacturing	accept?
360	Xinyuan Wang, Ruijie Liu, Haifa Qiu, Ben Tian, Deyi Chen, Yun Mou and Jianming Xu	Electro-Thermo-Mechanical Simulation Analysis of Al2O3, Si3N4 and AlN substrates for high power chip modules by double-sided cooling	Packaging Design & Modeling	accept?
361	Lei Sun, Xuanyu Chen, Peng He and Shuye Zhang	Microstructure and properties of Sn58Bi solder reinforced by TiN nanoparticles	Packaging Materials & Processes	ACCEPT
362	Junfeng Dou, Guisheng Gan, Fangliang Li, Junxiong Zhu, Qufeng Li, Daochun Xie, Mingli Geng, Daquan Xia and Xiangtao Xu	Effect of Welding Temperature on the Performance of Cu/Zn Foil + Cu Powder/Cu High-Temperature Joints	Power Electronics	ACCEPT
363	Fengjiang Wang, Zhenyi Ren and Xinfang Li	Low-temperature pressureless sintering of silver paste by ether-type solvents with different volatilization conditions	Packaging Materials & Processes	ACCEPT
364	Fangliang Li, Guisheng Gan, Junfeng Dou, Daochun Xie, Junxiong Zhu, Qufeng Li, Mingli Geng, Daquan Xia and Xiangtao Xu	The influence of welding temperature on the performance of Cu-foam Solid-solution joints under ultrasonic assistance	Power Electronics	ACCEPT
365	Qiang Wei, Weidong Liu, Xiaojian Ma, Huan Yang, Pengkai Wang and Jiachen Wang	Reliability leap In Electronic devices enabled by multiphysics-coupled model based on substrate traces	Packaging Design & Modeling	accept?
367	You Wang, Jian Zhang, Ming Zhao, Huijie Ye, Xiaomao Sun, Qian Lu and Chengju Liao	Analysis of Laser Ball Planting Process and Welding Strength Enhancement for 3D Heterogeneous SIP	Advanced Packaging	ACCEPT
368	Chunyang Wang, Litao Sun, Chunyan Yin and Guangbin Dou	Design and optimization of an adjustable natural frequency tuning fork structure	MEMS, Sensors and IoT	ACCEPT
369	Fangteng Gao, Pei Chen and Fei Qin	Edge-based smoothed finite element method for electro-thermo-mechanical simulation of TSV structures	Packaging Design & Modeling	ACCEPT
370	Qihang Zong, Chenshan Gao, Shizhen Li, Yihong Zhu and Huaiyu Ye	Mechanical Characterization of Sintered Ag Paste via Nanoindentation for Advanced Packaging in Power Electronics	Power Electronics	ACCEPT
371	Jinqian Huo, Yanfei Gong, Yuxin Wang and Liang Lou	Exploring low-temperature bonding of amorphous silicon thin films	MEMS, Sensors and IoT	ACCEPT

Paper ID	Authors	Title	Track	Decision
373	Michael Dong, Linda Li and Tina Hu	Research of wafer Polyimide layer opening size guideline to support WB ball shear test	Packaging Design & Modeling	ACCEPT
374	Zhijie Zhang, Zhiqian Li, Ziting Jin and Chunjing Shi	Effect of Gelatin and MPS on the Electrodeposition of (111)-oriented Nanotwinned Copper	Packaging Materials & Processes	ACCEPT
376	Zaiman Xiang, Zezhan Li, Xuyang Yan, Xuelang Wang, Jianjun Zhuang, Guoqi Zhang, Jiajie Fan and Wei Du	Microstructural Anisotropy-Governed Thermal Performance of Pressureless Sintered Silver in QFN Packaging	Power Electronics	ACCEPT
377	Xincheng Zhang, Na Liu, Bingxu Ma, Hang Liang, Haozhong Wang and Xiaofeng Yang	Thermal Failure Analysis and Reliability Optimization of Filter Chips	Quality & Reliability	ACCEPT
378	Zhizhen Wang, Dantong Song, Jianfeng Ye, Juan Yu, Jiazheng Wang, Yihan Xie, Xianglong Chu, Guangyao Li, Yelei Xie, Lihui Zhang, Zhongbao Hu and Shenglin Ma	Wafer-Level Integration of Liquid Cooling Microchannel on CMOS Chips with Cu-Cu Low-Temperature Bonding Process	Emerging Technologies	ACCEPT
379	Haowei Lu, Shineng Ma, Hao Luo, Xuewei Ding, Guangyao Li and Keqing Ouyang	AI-Driven Chip-Package-PCB Co-Design Method for FCBGA Package in Broadband Application	RF Electronic Packaging	accept?
380	Wenchao Wang, Hubing Wang, Delong Qiu and Chuan Chen	The Impact of Flow Conditions Control Method on Chip Thermal Dissipation in Immersion Liquid Cooling Systems	Emerging Technologies	ACCEPT
381	Kaifeng Wang, Shang Wang, Jiayun Feng, Yiping Wang, Pengrong Lin, Gehui Sun and Yanhong Tian	Constitutive Behavior and Failure Mechanism of SAC305 under Electro- Mechanical Coupling conditions	Quality & Reliability	ACCEPT
382	Jie Zhou, Pei Chen and Fei Qin	Flow field analysis of coolant in grinding process of silicon carbide wafer	Quality & Reliability	ACCEPT
384	Ziying Li, Qingyuan Tang, Bo Luo and Xiangsheng Ma	Effect of Processing Condition on Reliability Performance of SiC package by Pressure-less Silver Sintering	Packaging Materials & Processes	ACCEPT
385	Qiqi He, Xin Zhang, Weijian Zhang, Jinsong Fang, Yong Zhang and Yan Zhang	MDS Study on the Thermal Conduction of Hybrid Graphene-CNT and Graphene-CNW	Packaging Design & Modeling	ACCEPT
386	Zhihao Guo, Zhenchao Li, Susu Li, Han Jiang, Zhihong Zhong, Yaohua Xu, Kuijing Song and Shuibao Liang	Investigating the Effect of Temperature Gradients on Crack Propagation and Performance Degradation of SiC Power Modules with Sintered Silver Die Attach	Advanced Manufacturing	ACCEPT
388	Zihao Han, Liang Yang, Zhihao Jiang, Tiqun Wei and Jianwei Dao	Luminescence Properties and Thermal Stability of The Near-UV-Excitable Ce3+/Eu3+ co-Doped Ca3Bi(PO4)3 Red Phosphors for White LEDs	Optoelectronics and New Display	accept?
389	Yuanyuan Yang, Ruoyu Zhang, Zihao Liu, Caiping Zhu, Gang Li, Pengli Zhu Zhu and Rong Sun	Research of toughener to flowability and reliability of Underfill in 2.5-D Packaging	Quality & Reliability	ACCEPT

Paper ID	Authors	Title	Track	Decision
390	Deyu Lin and Yufang He	A Extreme Low Loss &Low CTE Build-up Resin Film For FCBGA	Packaging Materials & Processes	ACCEPT
391	Yiming Liu, Lu Han, Liang He, Yao Chen and Xiaotong Guo	Study on the limited role of traditional failure analysis methods in the drift-induced failures of SiC power devices	Quality & Reliability	ACCEPT
392	Zhihao Jiang, Liang Yang, Zihao Han, Tiqun Wei and Jianwei Dao	$Ba_5SiO_4Br_6:Bi^{3+}$: A Broadband Cyan Phosphor for Full-Spectrum White Lighting	Optoelectronics and New Display	accept?
393	Hao Zeng, Haitao Fu and Xiaohong Yang	Lead-free hybrid manganese(II) halides nanoparticles as highly-efficient and stable β-ray scintillators	Optoelectronics and New Display	ACCEPT
394	Guanqiang Song, Du Tao, Yuhong Li, Jing Jiang and Jianhui Liu	Research on dual-sided heat dissipation of power devices based on Panel-level package	Advanced Packaging	ACCEPT
395	Xin Wang, Yiming Liu, Ganqiang Wang, Lu Han, Yao Chen and Xiaotong Guo	Burn-out failure analysis of SiC MOSFET power device after HTRB test	Quality & Reliability	ACCEPT
396	Li Hongpeng, Wang Yanling, Li Kangrong and Yang Qiao	Data-Driven Distributed Parameter Extraction and PDK Design for Heterogeneous Interconnects	Packaging Design & Modeling	ACCEPT
397	Yiping Wang, Zirui Tong, Peng Wu, Jiayun Feng, Shang Wang and Yanhong Tian	A Novel Liquid Metal Composite Ag_2Ga Nanoneedle Paste Enabling Low-Temperature Sintering and Enhanced Performance in Power Device Packaging	Emerging Technologies	ACCEPT
398	Ping Wu, Zhen Liu, Yiou Qiu, Mingming Yi, Linzheng Fu, Lanying Xu, Wenhui Zhu and Liancheng Wang	Comparative Analysis of Substrate Equivalent Methods and Their Applications in Warpage Evaluation for Large Scale FCBGA Package	Packaging Design & Modeling	ACCEPT
399	Jianchao Liang, Ruyu Tian, Shang Wang, Shuai Wang, Wei Wang and Yanhong Tian	A novel lead-free solder alloy with high strength-ductility by doping rare Bi and Zi into SnAgCu solder alloy	Emerging Technologies	ACCEPT
400	Na Ya, Qidong Wang and Che Song	The Sampled-Data Modeling for Multiphase Constant-On-Time Control—Phase Overlapping	Power Electronics	ACCEPT
401	溢 杨, 博 徐, 禹 曹, 宝京 朱, 滨 韩, 玮 陈, 坤 何 and 衍行 王	Study on Microstructure and Performance Optimization of BaO– B_2O_3–SiO_2 Glass-Ceramic/ZrO_2 Composites	Packaging Materials & Processes	ACCEPT
402	Min Wang, Chengwei Zhang and Shengzhe Liu	Research on Efficient Localization Methods for Different Types of Capacitor Failures in Integrated Circuits	Quality & Reliability	ACCEPT
403	Wenting Liang, Yiheng Rao and Hao Wang	Miniature 3D TSV Differential Transformers for RFIC	RF Electronic Packaging	accept?

Paper ID	Authors	Title	Track	Decision
404	Haley Fu, Prabjit Singh, Raiyo Aspandier, Richard Coyle and Brian Franco	Some fundamentals of eutectic Sn-Bi and SAC305 solders metallurgy and electromigration	Packaging Materials & Processes	ACCEPT
406	Menghua Wang, Dan Yang, Liyi He, Shuanshe Chao, Xiao He and Na Mei	Analysis of the Influence of Package Size and Pin Type on CDM Peak Current	Quality & Reliability	ACCEPT
409	Menghua Wang, Dan Yang, Chang Liu, Niuyi Sun, Xiao He and Na Mei	Systematic Study of HK/MG TDDB Reliability under Different Bias	Quality & Reliability	ACCEPT
410	Yang Xuan, Shilu Zhou, Niuyi Sun, Shuanshe Chao, Xinyi Lin, Dan Yang and Na Mei	Impact of Dimensional Effect, Local Temperature and IMC Growth on Electromigration-Induced Degradation in SACQ Solder Ball：A Correlation Analysis	Quality & Reliability	ACCEPT
411	Fangmeng Xu, Chunyan Yin, Guangbin Dou and Litao Sun	A four-step wet etching technique for AT-cut quartz crystals incorporating a pre-trimming process for inverted-mesa type quartz resonators	MEMS, Sensors and IoT	ACCEPT
412	Yang Xi, Sheng Liu, Shizhao Wang, Zhiqiang Tian, Rui Li, Bo Zhao and Shi Zhang	Study of the effect of hybrid bonding interface defects on the copper diffusion mechanism	Advanced Packaging	ACCEPT
413	Shirong Li, Fei Qin and Ge Shi	Simulation of Solder Ball Reliability of LTCC RF SiP Components under Thermal Cycling Load	Quality & Reliability	ACCEPT
414	Yinzuo Qian, Shuanshe Chao, Shaobing Lin, Yuyang Zhan, Dan Yang and Na Mei	Investigation of Short-Circuit Failures Caused by Circuit Design and Wafer Defect	Quality & Reliability	ACCEPT
415	Zhichao Liu, Jingyan Li, Hanqiang Wu, Penghui Guan, Xianli Xie and Yiying Zhu	Effect of crystalline structure on the thermal expansion behavior in hybrid bonding: A molecular dynamics simulation	Advanced Packaging	ACCEPT
416	Xianshan Dong, Xinlong Huang, Guoguang Lu, Wei Su, Qinwen Huang and Changjian Zhou	Reliability Model for Vacuum Packaged MEMS Devices Considering Multiple Failure Mechanisms	Quality & Reliability	ACCEPT
417	Ge Shi, Fei Qin and Shirong Li	Reliability of LTCC RF SiP plate antenna solder ball under random vibration simulation	Quality & Reliability	ACCEPT
418	Ningning Xu, Dongchen Fan, Yi Zhong and Daquan Yu	Warpage Mitigation in 2.5D Chiplets Packaging through Heterogeneous Integration of Diamond Heat Spreaders	Emerging Technologies	ACCEPT
419	Fei Pan, De-Xiang Zhou, Jian-Hui Liu, Rui-Feng Sun and Jun Liu	Design and Fabrication of a Ceramic-Based Interposer	Interconnection Technologies	ACCEPT
420	Anqi Zhou, Yu Zhang, Fei Ding, Renxi Jin, Qidong Wang and Liqiang Cao	Investigation of Dielectric Materials in D2W Bonding: SiO2-SiO2, SiO2-SiCN, and SiCN-SiCN	Advanced Packaging	ACCEPT

Paper ID	Authors	Title	Track	Decision
421	Xiaomao Sun, Chengju Liao, Qian Lu, Jian Zhang, Xin Kong, Wenhan Chang and You Wang	Study on Chipping Control in Laser Stealth Dicing Technology for GaAs Chips	Advanced Manufacturing	ACCEPT
422	Chunyu Lan, Gaowei Xu, Haijian Zhao, Yang Huang and Bojun Chen	Effect of Underfill on the Reliability of Indium Flip-Chip Interconnections Under Cryogenic Thermal Shock	MEMS, Sensors and IoT	ACCEPT
423	Yukai Xia, Haoran Ma, Zhou Gui, Tianhao Guo and Yiyang Cai	A Physics-Informed Convolutional Neural Network for Predicting Electromigration Lifetime in Copper Interconnects	Packaging Design & Modeling	accept?
424	Xuze Li, Yu Zhang, Fei Ding, Renxi Jin, Qidong Wang and Liqiang Cao	A novel two-step activation to control copper oxidation for small-pitch Cu/SiCN hybrid bonding	Advanced Packaging	ACCEPT
425	Xiaoran Cheng, Zhaoxi Wu, Zhimin Ding, Chao Duan, Wei Sun and Meng Meng	Failure Mechanism Investigation of Silver Conductive Adhesive Peeling in Hermetically Sealed Semiconductor Device	Quality & Reliability	ACCEPT
426	Yanming Zhang, Ce Zeng and Yang Li	Unified Convolutional Neural Network Framework for Thermomechanical Modeling of Substrate with Multi-materials	Packaging Design & Modeling	ACCEPT
427	Ruijiao Qin, Xi Liu and Anxue Zhang	Research on Packaging Technology of Micro-Module Based on 3D-TSV Integration and Micro-Assembly	Advanced Packaging	ACCEPT
428	Feiyang Pan, Chunyan Yin and Guangbin Dou	Automated Mesh Generation in FEM: A Novel Approach Using Large Language Models	MEMS, Sensors and IoT	ACCEPT
429	Tina Li, Tim Feng and Joey Jiang	Electrolytic Cu Plating and Anti-tarnish Influence on Cu Layer Oxidation	Packaging Materials & Processes	ACCEPT
430	Xu Long, Sijia Zhang and Hongbin Shi	Fracture mechanism of porous polycrystalline sintered silver revealed by CP-FEM and CZM	Packaging Design & Modeling	ACCEPT
432	Shuanzhu Fang, Pengwei Zhu, Yongle Zhong, Yuqiao Zhang, Zhizhe Wang, Jun Luo, Yuping Zhao and Kun Jiang	Research on Junction Temperature Measurement of SiC MOSFETs Using Electrical Methods and Infrared Thermal Imaging	Quality & Reliability	ACCEPT
433	Qian Ma, Zhaoling Huang, Chengqi Ge, Hao Zhou, Zhiyan Guo and Qi Zeng	Interfacial Damage Behavior Analysis in Polyimide-Copper/Titanium Hybrid Structures	Quality & Reliability	ACCEPT
434	Shuanzhu Fang, Yumeng Tang, Xuexian Wei, Ping Guo, Yongle Zhong, Sha Tang, Yuping Zhao, Zhizhe Wang and Jun Luo	Research on Surge Current and Avalanche Voltage Reliability Testing of 1200V SiC MOSFETs	Quality & Reliability	ACCEPT
435	Junju Xu, Minglu Xia, Ziyang Gao, Chun Kit Cheung and Haihui Ruan	Investigation of Thermal Performance in Pin-fin Baseplate for High-Density SiC Power Modules	Power Electronics	ACCEPT

Paper ID	Authors	Title	Track	Decision
436	Ziqi Lian, Yu Zhang, Fei Ding, Renxi Jin and Qidong Wang	Particles generation and mechanism analysis in plasma activation for direct D2W hybrid bonding	Advanced Packaging	ACCEPT
438	Xu Kong, Shu Y. Ma, Dong Z. Fu and Zhi Y. Xiao	Wafer level single via process for image sensor	Interconnection Technologies	accept?
439	Xu Long, Xiaohan Ma, Ming Liu, Bin Yang, Hongbin Shi and Chengqiang Cui	Mechanical behavior of glass with different roughness and its influence on TGV reliability	Packaging Materials & Processes	ACCEPT
440	Chaoyang Zhang, Mulan Li, Shijun Huang, Jingwen Liu, Zifeng Ding and Cai-Fu Li	Study on the Oxidation Behavior During the Sintering of Silver Paste Promoted by Oxygen	Packaging Materials & Processes	ACCEPT
441	Yuyang Zhan, Shuanshe Chao, Xinyi Lin, Xiao He, Dan Yang and Na Mei	Investigation on Raido Frequency Intergrated Circuit Gain Degradation Caused by Electrical Overstress	Quality & Reliability	ACCEPT
442	He Shengzong	Scenario-Adaptive Reliability Evaluation of TMR Current Sensors: A Structural-Failure Co-Analysis Framework for High-Reliability Applications	Quality & Reliability	ACCEPT
445	Wu Yixiong, Du Yunhui, Fan Dongchen, Zhong Yi and Yu Daquan	Low-temperature Heterogeneous Integration of Ga_2O_3 Devices with Diamond for Enhanced Thermal Management in High-Power Electronics	Power Electronics	ACCEPT
448	Mingli Geng, Guisheng Gan, Jie Luo, Wenhao Luo, Ruizhe Xing, Yuhang Pan, Kai Qin and Qiao He	Effect of Cu nanoparticle addition on thermal reliability of Al/SAC0307+Zn/Cu joints	Quality & Reliability	ACCEPT
449	Yikai Zeng, Xiang Wang, Jianqiang Li and Tong An	Analysis of the impact of major process steps on bond wire stresses in novel optical random source chip packaging	Quality & Reliability	ACCEPT
450	Piao Yang and Aiying Guo	Application of Visual Redundancy in Optical Display	Optoelectronics and New Display	ACCEPT
451	Guisheng Gan, Mingli Geng, Jie Luo, Wenhao Luo, Ruizhe Xing, Yuhang Pan, Kai Qin and Qiao He	Effects of different adding methods of Cu nanoparticle on the properties of Al/Cu joints with ultrasonic assistance	Packaging Materials & Processes	ACCEPT
452	Zhuangchao Zhan, Quantao Liang, Wenchao Wen, Jizhan Lin, Zejiong Yu, Jian Huang, Daoguo Yang and Hongbo Qin	Effect of Copper Residual Ratios of High-Density PCB on Chip Warpage During Die Bonding Process	Packaging Design & Modeling	ACCEPT
453	Wei Liu, Chunyan Yin and Guangbin Dou	Design and Genetic Algorithm Optimization of a High-Shock-Resistant MEMS Accelerometer Sensitive Structure for Automotive Airbag Applications	MEMS, Sensors and IoT	ACCEPT
454	Hao Cheng, Chuantao Hou, Yueping Zhang and Yao Li	Determinations of thermal strains in electric packaging: experiments and simulations	Quality & Reliability	ACCEPT

Paper ID	Authors	Title	Track	Decision
456	Rui Cao, Zhongxin Yang and Zheng Wang	Investigation of Connection Performance and Failure Mechanisms of Sealed Crimp Connectors for Copper-Clad Aluminum Wires	Quality & Reliability	ACCEPT
457	Chenghao Yuan, Zhensong Li, Yanfei Gong and Yanxiao Zhao	Analytical Modeling for the Radiation Characteristics of the GCPW to Quasi-Coaxial Structure in High-Speed Interconnection of SiP	Packaging Design & Modeling	ACCEPT
458	Yue Zhao, Ying Ren, Jun Luo and Qiuzhen Zhang	Research on Chip Surface Character Recognition Method Based on Improved YOLOv7-tiny and CRNN	Emerging Technologies	ACCEPT
460	Huiyu Chang, Yingtao Ding, Ziyue Zhang, Han Wang, Anda Zhang and Zhiming Chen	Design and Simulation of a Novel Integrated Opto-Electronic Through-Glass-Via (TGV) Structure for Co-Packaged Optics (CPO) Applications	Interconnection Technologies	ACCEPT
461	Guanghua Yuan, Xianjun Kuang, Xingxian Xia, Xiaoling Lin, Xiaofeng Yang, Gaoming Shi, Weijian Zhou and Chao Li	Failure Mechanism of Electrochemical Migration Silver Electrode on Negative Temperature Coefficient Thermistor in Intelligent Power Module	Quality & Reliability	ACCEPT
462	Jianfang Zhu, Shikang Liu, Dongdong Shao and Kunpeng Ding	A Fan-Out Panel Level Packaging (FOPLP) Structure Achieving Double-Sided Die Bonding Interconnects Through Copper Through-mold Vias (TMVs)	Advanced Packaging	ACCEPT
463	Lezhi Ye, Congcong Yu and Wen Meng	Analysis of angular stiffness characteristics of the aerostatic spindle of a wafer grinder based on a nonlinear spring	Advanced Manufacturing	ACCEPT
464	Tianhan Liu, Xinbin Guan, Jianming Fang, Xuanlong Chen and Gaoming Shi	The Application of High-Precision 3D X-ray Microscopy in the Failure Analysis of Integrated Circuits	Quality & Reliability	ACCEPT
466	Yingyu Liu, Qiao Yang and Ruijiao Qin	Design of an Implantable Antenna for Wireless Brain-Computer Interface	RF Electronic Packaging	accept?
467	Yikun Zhang, Guangbin Dou and Chuanyan Yin	Intelligent ECG Monitoring System Based on DenseNet with Portable Deployment	MEMS, Sensors and IoT	ACCEPT
469	Xiaoliang Ji, Yishu Wang, Fu Guo and Chunqing Wang	Mechanistic insight into cryogenic brittle fracture of β-Sn: A comprehensive study	Interconnection Technologies	ACCEPT
470	Mengke Yang, Qiuxi Li and Xiaowei Wang	Solution for solder joint reliability with radio energy efficiency features	Quality & Reliability	ACCEPT
471	Ziniu Yu, Yuqi Zhou, Yuhan Gao, Xin Lei, Yuxin Chen, Kezhong Xu, Chuanjia Wang, Jianguo Xie and Fulong Zhu	Multiscale Investigation on Properties of Silver-Coated Copper Electrically Conductive Adhesives	Packaging Materials & Processes	ACCEPT
474	Bo Zhao and Jun Liu	Nano-TSV Fabrication for 3D Interconnection	Interconnection Technologies	ACCEPT

Paper ID	Authors	Title	Track	Decision
475	Zihao Song, Danlei Wang, Kaixuan Nie, Zhe Li and Rong Sun	Regulating the end-group adsorption of levelers in redistribution layer copper electroplating for high-density advanced packaging	Packaging Materials & Processes	accept?
476	Rui Zhou, Tong An and Fei Qin	Bond wire stress analysis of IGBT module under vibration loading and low junction temperature differential power cycling	Quality & Reliability	ACCEPT
477	Jiasheng Liu, Haoran Ma, Zeen Ren, Yiyang Cai, He Yu and Xushuo Zhang	A New Preparation Scheme of Low Temperature Copper Paste	Power Electronics	ACCEPT
478	Zhi Lin	The Morphology of Creep on Solder Joint under Different Condition of Temperature and Stress	Quality & Reliability	ACCEPT
481	Yuhan Gao, Yuxin Chen, Ziniu Yu, Yuqi Zhou, Kezhong Xu, Chuanjia Wang, Jianguo Xie and Fulong Zhu	In-situ Measurement Method for Warpage of Electronic Package Substrate Based on Speckle-free DIC and Carbon Coating	Advanced Manufacturing	ACCEPT
485	Guangjun Zhang, Martin Letz, Volker Seibert, Fabian Wagner, Inge Burger and Ulrich Peuchert	On the mechanic reliability of structured glasses as substrates in advanced packaging applications	Advanced Packaging	ACCEPT
487	程 彭, 思维 孙, 秋实 康, 丰满 刘, Qidong Wang and Liqiang Cao	Mechanism of Stress Distribution at the III - V/Si Heterogeneous	Quality & Reliability	ACCEPT
488	Yuxin Ye, Ruiwen Liu, Peijie Li, Yanmei Kong, Guoran Lu, Xinhao Meng, Jingping Qiao, Jianliang Shen and Binbin Jiao	Silicon-based direct liquid cooling module for system on wafer	Advanced Packaging	ACCEPT
489	Song Ding, Qi Liu and Qinsong Qian	Internal Stress Relief and Efficiency Improvement Method of PSiP Power Module Based on Surface Grinding and Post-curing Approach	Power Electronics	ACCEPT
490	Qiao Yang, Kangrong Li and Yanling Wang	Optimization of via design in ceramic substrate based on quasi-static electromagnetic simulation	Packaging Design & Modeling	accept?
491	Lulin Xie, Kingning Tu and Yingxia Liu	Investigating the Oxidation Resistance of Nanosized SnBiIn Solder Through TEM Analysis	Advanced Packaging	ACCEPT
492	Quanlu Zhao, Jingyi Zhao, Chuan Chen, Qidong Wang, Shanjun Ding and Xiaomeng Wu	Dicing Failure Mechanism and Structural Optimization for Large-Format Multilayer Glass Substrates	Quality & Reliability	ACCEPT
493	Yuxin Deng, Xiaodong Jian, Si Chen, Yu Zhao, Xiaofeng Yang, Nan Hua, Bin Zhou and Guoguang Lu	Effect of Defect Type on Structural Strength and Thermal Properties of Si/Ti, Ti/Au, Ti/Au, and Au/Au Interfaces	Quality & Reliability	ACCEPT
494	Jianming Fang, Chengwei Zhang and Zihao Liu	Study On Failures Of Silver Bonding Wire In Real-World Applications	Quality & Reliability	ACCEPT

Paper ID	Authors	Title	Track	Decision
495	Feng Zhu, Yangming Liu, Bo Yang and Ning Ye	ELK Stress Simulation and Parameter Optimization Design in Flip Chip Packaging	Packaging Design & Modeling	accept?
496	Haojie Zhou, Boyan Zhao, Min Wu, Guoxu Fang, Xiaoxiao Ji, Luqiao Yin and Jianhua Zhang	Micro-LED Array with 370×110 Resolution for Digital Headlights	Optoelectronics and New Display	ACCEPT
497	Zhijun Long, Chenxi Yang, Jianguo Zhang, Bin Yu, Guanghao Zeng, Zhen Zhang, Guangyao Li and Keqing Ouyang	The Simulation and Testing of UCIe Power Noise Based on Chiplet	Packaging Design & Modeling	ACCEPT
498	Wanbin Yang, Hao Yang, Sha Xu, Chunbing Guo and Fa Dai	Thermal Reliability Analysis and Optimization of Millimeter-Wave Multi-Chip RF Front-End Modules under High-Density Packaging	Quality & Reliability	ACCEPT
499	Meiyu Wang, Zhuo Pang, Yiting Han and Zewei Zhang	Stress Relief of Power Module Using Sintered-Silver Die Attachment in Cylinder-Grid-Array (CGA)	Packaging Design & Modeling	ACCEPT
500	Jinzhu Li, Qichun Lou, Ziyu Liu, Mingze Ban, Zeyu Ning, Chuandong Li and Qingqing Sun	Measurement and improvement of PI surface energy applied for novel PI-Cu hybrid bonding	Interconnection Technologies	ACCEPT
501	Zhen Sun, Xin-Ping Zhang, Jia-Ao Chen, Ming-Sheng Luo and Guang-Chao Lyu	The Interfacial Delamination and Fracture Behavior of Cu-filled TGV Interposer Package with Multi-Layer RDLs under Thermo-mechanical Loads	Quality & Reliability	ACCEPT
502	Bowen Cai, Zhong Lian, Qi Zhang, Zhi-Quan Liu and Changyou Ren	Investigation on the interfacial behavior and interconnection reliability of adhesion layer for gold-silver wire bonding	Advanced Manufacturing	ACCEPT
503	Lei Wang, Chengyang Luo, Quan Huang and Guoguang Lu	A New Electromagnetic Probe With high Sensitivity and Low Profile For Near-field Test	Quality & Reliability	ACCEPT
505	Yanchen Li, Ruichong Li, Li-Yin Gao and Zhi-Quan Liu	Study on the oxidation mechanism of electroplated copper with different grain orientations	Packaging Materials & Processes	ACCEPT
506	Haokang Zhang, Dekun Yang and Lingjie Li	Design of LSPR optical memory based on angle-resolved scattering measurement	Optoelectronics and New Display	ACCEPT
507	Lingjie Li, Dekun Yang and Haokang Zhang	Deep Learning Based Angle-Resolved Critical Dimension Metrology for 3D NAND Channel Hole Structures	Optoelectronics and New Display	ACCEPT
508	Yichi Pan and Dekun Yang	TSV Measurements Of Angle-Resolved Scattering	Optoelectronics and New Display	ACCEPT
509	Zijun Luo, Ke Zhang, Liang He, Zhiyuan He, Yijun Shi, Xinghuan Chen and Yuan Chen	Performance Degradation of the Schottky p-gate GaN HEMT Under Power Cycling	Quality & Reliability	ACCEPT

Paper ID	Authors	Title	Track	Decision
510	Yunting Zhu, Yicheng You, Hailang Wen, Ke Li, Xueer Chen, Weiyi Lin and Daquan Yu	Assembly of diamond microstructures in 3D package system for efficient thermal dissipation	Emerging Technologies	ACCEPT
511	Qian Zhou, Guangjun Lu, Hongqing Wei, Jiande Su and Jia Nie	Fabrication of blue perovskite light-emitting devices based on planar printing technology	Optoelectronics and New Display	accept?
512	Feng Xie, Shouliang Hu, Yuefang Li, Hu Chen and Wei Zhong	Investigation on the brazing interface failure assessment of SiP ceramic envelope under multi-axial stress	Quality & Reliability	ACCEPT
513	Yonglin Xia, Yufei Sheng, Jiaxuan Xu and Hua Bao	Phonon Boltzmann Transport Equation-Based Thermal Simulation and Effective Thermal Conductivity Extraction of FEOL for 3D Advanced Packaging Thermal Management	Packaging Design & Modeling	ACCEPT
514	Ru Jia, Xinyu Zhang, Yufei Sheng and Hua Bao	Analysis of Self-Heating Effects in Cryo-CMOS technology Modeled by Phonon Boltzmann Transport Equation	Packaging Design & Modeling	accept?
515	Genghua Zhang, Fangyuan Zeng, Qi Zhang and Zhiquan Liu	The effects of additives on impurities, microstructure, and reliability of copper coatings	Packaging Materials & Processes	ACCEPT
516	Xin-Ping Zhang, Jia-Wei Deng, Ming-Sheng Luo, Can Zhao, Pu Xu, Si-Yuan Wang and Ming-Bo Zhou	Reducing Splashing and Residual Defects in Laser Soldering: Optimization of Process Parameters and Development of a adapted Solder Paste	Packaging Materials & Processes	ACCEPT
517	Yonggui Chen, Zhengwei Fan, Kaihong Hou, Shufeng Zhang, Yashun Wang and Xun Chen	The effect of different copper defect shapes on the behavior of TSV under thermal cycling	Quality & Reliability	ACCEPT
518	Xin Chen, Jingyu Lin and Daquan Yu	Low-loss Substrate Integrated Waveguide Bandpass Filter Based on Through Glass Via for Millimeter Wave Application	Advanced Packaging	ACCEPT
519	Kuiyu Xiao, Lianqiao Yang and Ming Li	Multi-physics coupling analysis of hybrid bonding based on finite element analysis	Interconnection Technologies	accept?
523	Jiahao Yin, Nan Huang, Lanyu Zhang and Jian Gao	Development and test of a high precision walker-type inchworm piezoelectric motor	Advanced Manufacturing	ACCEPT
524	Jian-Wei Xian, Xin-Ping Zhang, Hai-Ping Li, Hui-Qian Zhou and Xiao Ma	A Novel Large-Area Photoresist Removal Process for Multi-wafer in Advanced Packaging by Surface Wave Plasma	Advanced Manufacturing	ACCEPT
525	Zhiyu He, Zheyao Wang and Kai Zheng	Finite Element Analysis of the Impact of Copper Density on Hybrid Bonding Interfacial Stress	Packaging Design & Modeling	ACCEPT
526	Daquan Yu, Zhan Meng and Xuesong Quan	Copper Filling of Taper-Free High-Aspect-Ratio Diamond Through Holes for Fabricating Integrated Passive Components	Interconnection Technologies	ACCEPT

Paper ID	Authors	Title	Track	Decision
527	Jianming Fang, Jinzhou Li and Xinbin Guan	Failure Analysis of Bonding Crater Damage in Gold, Copper, and Silver Wire	Quality & Reliability	ACCEPT
528	Hongqing Wei, Guangjun Lu, Qian Zhou, Jiande Su and Jia Nie	Introducing a synergistic strategy of multifunctional small molecules and gradient optimization of hole transport layer to prepare efficient and stable blue perovskite	Optoelectronics and New Display	accept?
529	Zhiqiang Huang, Lingfeng Deng, Min Wang, Jianxiong Liu and Xuanlong Chen	Failure Analysis of RF Switches Combining FIB Circuit Modification and OBIRCH Localization	Quality & Reliability	ACCEPT
530	Haikun Yue, Wenbo Luo and Yang Tang	A W-band Phased Array Antenna-in-Package (AiP) Based on Glass Substrate	Advanced Packaging	ACCEPT
531	Chen Lijun, Feng Chen and Fengwei Dai	Thickness controllable 3D NAND flash package with wafer-level fan-out packaging	Advanced Packaging	ACCEPT
532	Chen Ma, Xudong Xu, Xi He, Zhiyu Wang, Feixuan Huang, Lihang Liao and Nan Wang	Coupling Coefficient Enhancement Achieved by Floating Electrodes on AlN Thin Film Resonators	RF Electronic Packaging	ACCEPT
533	Ying Tian, Shiyuan Wang, Daquan Yu, Li Yan, Miao Zhang and Meng Wei	Application Research on Chip Bonding Technology for Highly Integrated SiP Devices	Emerging Technologies	ACCEPT
534	Bie Xiaorui, Zheng Wang, Kunfeng Wang, Wuhao Yang, Zhitian Li and Xudong Zou	Analysis of thermal hysteresis in silicon resonant accelerometers caused by packaging stress	MEMS, Sensors and IoT	ACCEPT
535	Xuetao Yan, Xiangxu Meng, Siwei Sun, Yetong Zhang, Fengman Liu and Qidong Wang	Modeling and Optimization of Nonlinearity in PIN-Type Position Sensitive Detectors: A Combined Theoretical and Numerical Approach	Optoelectronics and New Display	accept?
536	Xing Zhou, Yuxin Ye, Yanmei Kong, Ruiwen Liu, Binbin Jiao, Zihang Yuan, Shuxiang Wang, Xinhao Meng and Zilong Wang	Embedded Microfluidic cooling for System on wafer: thermal design and CFD simulation	Advanced Packaging	ACCEPT
537	Zihang Yuan, Yuxin Ye, Yanmei Kong, Ruiwen Liu, Binbin Jiao, Xing Zhou, Shuxiang Wang, Guoran Lu and Ruihai Su	The study of embedded microfluidic cooling for chip thermal management at KW/cm^2 level	Advanced Packaging	ACCEPT
538	Hai Huang, Quanlu Zhao, Chuan Chen, Meiying Su, Rong Fu and Jun Li	Active Thermal Management Strategy and Mathematical Modeling for System-Level Packaged Modules in Logging-While-Drilling Systems	Packaging Design & Modeling	ACCEPT
539	Dou Xu, Gaohui Xu, Xinyi Shi, Yujian Wang and Wanli Li	Low-Temperature Copper Sintering Bonding Technology Based on Non-Spherical Bimodal Design and Solvent Optimization	Packaging Materials & Processes	ACCEPT
540	Donglin Cao, Kechen Zhao, Xiaoyu Guan, Chufei Cheng, Jiwen Zhao, Bing Dai and Jiaqi Zhu	High-temperature resistant wafer-level temporary bonding by W release layer for diamond growth	Packaging Materials & Processes	ACCEPT

Paper ID	Authors	Title	Track	Decision
541	Zikang Luo, Xiuqi Wang, Jingyuan Ma, Yifan Li, Pengjie Zhou and Hongjun Ji	Ultrasonic-assisted wetting behaviors of Sn solder on (111) nano-twinned Cu electroplating films for UBM	Packaging Materials & Processes	ACCEPT
542	Jiahao Yu, Pingjuan Niu, Pingfan Ning and Jie Liu	Reliability Analysis and Lifetime Prediction of Low-Inductance Double-Sided Cooling SiC Power Modules	Quality & Reliability	ACCEPT
543	Yuqiang Zhang, Haiyun Xue, Yu Zhang, Fengman Liu and Qidong Wang	Etch-Free Lithium Niobate Electro-Optic Modulator with 110 GHz Bandwidth: Simulation Design and Performance Optimization	Optoelectronics and New Display	ACCEPT
544	Yifan Li, Xiuqi Wang, Zikang Luo, Mingyu Li and Hongjun Ji	Diect low-temperature sintering of Cu nanoparticles on laser-metallized AlN ceramics by UV nanosecond laser	Packaging Materials & Processes	ACCEPT
545	Lai Wei and Guoqi Zhang	Metallic Sintering Interconnect using on-substrate microheater	Optoelectronics and New Display	accept?
547	Hao Guan, Yifei Chang and Pan Liu	Simulation, Verification, and Failure Analysis of 1.2kV Planar-Gate SiC MOSFET Under Surge Current Stress of Body Diode	Power Electronics	ACCEPT
548	Kexuan Zhang, Yang Qiu, Xingyan Zhao, Shaonan Zheng, Yuan Dong, Qize Zhong and Ting Hu	A Concave-Convex Cu Interconnect Pair Structure for Cu-Cu Direct Bonding with Self-alignment Capability and Enhanced Shear Strength	Packaging Design & Modeling	accept?
549	Xiuqi Wang, Pengjie Zhou, Dashi Lu, Mingyu Li and Hongjun Ji	CuAgSnIn nanoparticle composite joints with rapid bonding and high shear strength for power electronics packaging	Power Electronics	ACCEPT
550	Gong Mingjie, Huang Dong and Shi Hailin	Research on advanced manufacturing mode of high reliability hybrid integrated circuit	Advanced Manufacturing	ACCEPT
551	Guoqiang Zhao and Yi Zhao	Finite Element Modeling of the Effects of Copper Density on Bonding Strength and Interfacial Stress in 1 μm Pitch Hybrid Bonding	Interconnection Technologies	accept?
552	Zhixin Sheng, Rui Cao, Huimin He, Bowen Zhou, Xianpeng Chen, Haiyun Xue, Fengman Liu and Qidong Wang	Research on high-density and high-efficiency optical coupling packaging of 100 Gbps vertical cavity laser emitter array for CPO	Optoelectronics and New Display	ACCEPT
553	Bowen Zhou, Rui Cao, Huimin He, Zhixin Sheng, Xianpeng Chen, Haiyun Xue, Fengman Liu and Qidong Wang	Skin Depth Considerations: How Copper Roughness Degrades Differential Signal Propagation Above 100Gbps	Optoelectronics and New Display	ACCEPT
554	Hao Wang, Lihang Liao, Chen Ma, Xudong Xu, Ziyi Ge, Xitong Wang, Renzhe Li, Lekang Lin, Zhiyu Wang and Nan Wang	Design of Wideband Hybrid Bandpass Filter with Steep Roll-off and High Out-of-band Rejection	RF Electronic Packaging	ACCEPT
555	Ziyi Ge, Chen Ma, Xudong Xu, Hao Wang, Lekang Lin, Renzhe Li and Nan Wang	Investigation on High Power Durability FBAR Devices	RF Electronic Packaging	ACCEPT

Paper ID	Authors	Title	Track	Decision
556	Jingsheng Liu, Baojun Qiu and Hui Tang	The Component Level Reliability Verification of An Automotive Grade Microcontroller	Quality & Reliability	ACCEPT
557	Kefu Zeng, Zehua Tang, Guannan Yang, Yu Zhang, Guanghan Huang and Chengqiang Cui	Surface metallization of glass substrate through an interlayer of glass-copper composite	Advanced Manufacturing	ACCEPT
558	Junxiong Zhu, Guisheng Gan, Junfeng Dou, Fangliang Li, Qufeng Li, Daochun Xie, Rongyu Chen, Daquan Xia and Xiangtao Xu	Effect of Nano-SAC0307 Content on Performance of Cu/Al Joints with Dual-Ultrasonic Synergism at Low Temperature	Packaging Materials & Processes	ACCEPT
559	Guandong Liu	Advanced Packaging-Compatible Vertical Micro-Lenses for Micro-Opto-Electro-Mechanical Systems	Optoelectronics and New Display	ACCEPT
560	You Zhi, Wang Linggen, Mu Wei, Tian Tiancheng, Wang Han, Chen Fengwen and Wang Yihao	stress analysis of power module during pressure sintering process	Power Electronics	accept?
561	Peng Sun, Yi Zhong and Daquan Yu	One-Step Electroless Copper Plating Enabled by Self-Assembled Silane Monolayers on Glass Substrate Surfaces	Emerging Technologies	ACCEPT
562	Xianpeng Chen, Rui Cao, Huimin He, Zhixin Sheng, Bowen Zhou, Fengman Liu and Qidong Wang	Impact of TSV Annealing Thermal Stress on Micro-Ring Modulator in 3D optical IO	Optoelectronics and New Display	ACCEPT
563	Zhiying Yu, Lingfeng Deng, Jianxiong Liu, Min Wang, Zhiqiang Huang and Xinbin Guan	An Innovative Failure Localization Method for Multi-layer Stacked Metal Capacitors in Integrated Circuits: Layer Thinning Combined with OBIRCH Technique	Quality & Reliability	ACCEPT
565	Gen Li	An Asymmetrically Interlocked Ultra-wide Sensing Range Capacitive Tactile Sensor With A Two-stage Enhancement Pyramid Microstructural	MEMS, Sensors and IoT	ACCEPT
566	Hailang Wen, Yunting Zhu, Yicheng You, Weiyi Lin and Daquan Yu	Large-Scale Interconnection for High-Power Diamond Radio Frequency Devices	Emerging Technologies	ACCEPT
567	Kewei Wu and Deyin Zheng	Enhancing Two-Phase Immersion Cooling for High-Power Chips through Integrated Vapor Chamber	Packaging Design & Modeling	ACCEPT
568	Zijun Luo, Shuqiang Liu, Xia Luo, Wanni Zhan, Jinbao Cai, Zhiyuan He, Yuan Chen and Liang He	Degradation Analysis of SiC MOSFETs Under High Temperature Gate Bias Stress Above 200°C	Quality & Reliability	ACCEPT
569	Hai-Ping Li, Xin-Ping Zhang, Jian-Wei Xian, Hui-Qian Zhou and Min-Bo Zhou	Process Optimization and Mechanism of Photoresist Removal using Remote Plasma in High-Aspect-Ratio Structures for Advanced Packaging	Advanced Manufacturing	ACCEPT
570	Xudong Xu, Chen Ma, Jiewei Jiang, Ziyi Ge, Zhiyu Wang, Feixuan Huang, Renzhe Li, Hao Wang, Lekang Lin, Chunmiao Qi and Nan Wang	Interdigital-shape Phononic crystal for the improvement of quality factor based piezoelectric-on-silicon MEMS resonators	RF Electronic Packaging	ACCEPT

Paper ID	Authors	Title	Track	Decision
572	Wang Chongyue, Guo Jianheng, Chen Biqi, Lin Renyi and Li Zongtao	Frequency-Division Multiplexed Quantum Dot-Polymer Optical Fiber Sensor for Distributed Gesture Recognition	Optoelectronics and New Display	accept?
573	Yue Tang, Huanpeng Wang, Kun He, Jie Liu, Musheng Liang and Yuehang Xu	Research on the Analysis of Fracture Failure Mechanisms in Heterogeneous Integration Interconnect Structures under Thermoelectric Coupling.	Quality & Reliability	ACCEPT
574	Shaodian Yang, Zheng Chen, Zhiqiang Lin, Zhengxun Hu and Rong Sun	Investigation of Wafer Warpage and Chip Misalignment in Advanced Packaging: Material-Process Interactions in wafer reconstruction techniques	Packaging Design & Modeling	accept?
575	Xinyi Wang, Youxing Zhang, Zhaoyu Chen, Haojie Zhou, Xiaoxiao Ji, Luqiao Yin and Jianhua Zhang	Dual Wettability Control of Coffee Ring Effect in QDCC Layer with BM	Optoelectronics and New Display	ACCEPT
576	Zhu Yang, Xiaoxiao Ji, Haojie Zhou, Guoxu Fang, Min Wu, Luqiao Yin, Xiuzhen Lu and Jianhua Zhang	Preparation of Blue GaN Micro-LED Array Based on Direct Laser Transfer and Thermocompression Bonding Process	Optoelectronics and New Display	ACCEPT
577	Weilin Liu, Cheng Yang and Haoyang Cui	Impact of Fault Voltage Duration on IGBT Junction Temperature in Converter	Power Electronics	ACCEPT
578	Ruiting Zhang, Zhiqiang Lin, Zhengxun Hu and Rong Sun	The Impact and Application of Hydrophilicity of Wafer Surface on Defect Removal Efficiency after CMP	Advanced Packaging	ACCEPT
579	Wen-Long Shao, Lin-Jie Liu, Zhen-Tao Yang, Xi-Meng Yu and Run-Zhang Wang	Design of a wideband Package for MMIC Applications Based on High Temperature Co-fired Ceramic	RF Electronic Packaging	accept?
580	Qiang Ping, Lei Yang, Lei Qiu, Jianwei Zong and Liang Lou	A NOVEL CANTILEVER-BASED MINIATURIZED PIEZOELECTRIC HYDROPHONE	MEMS, Sensors and IoT	ACCEPT
581	Ziyan Zhou, Lei Li, Qinsong Qian and Weifeng Sun	Optimized Design of 48-1V LLC-DCX Transformer Structure Based on Finite Element Analysis Achieving 1900W/in³ Power Density	Power Electronics	ACCEPT
583	Chen Peng, Fengze Hou, Rui Ma, Meiying Su, Yunyan Zhou, Qidong Wang, Zijun Zhong and Liqiang Cao	Warpage Analysis of RDL-First Fan-Out Packaging Using Solid-Shell Element and Reduced-Order Models	Packaging Design & Modeling	ACCEPT
585	Le Chen, Yu Zhang, Yuting Zhang, Yanzhe Xu and Qiang Ma	KSF/β-Sialon Phosphor System Innovations in Mini-LED Backlight Technology	Optoelectronics and New Display	ACCEPT
587	Jiawen Wen, Wenli Zhang, Zhan Wang, Zewen Li and Guanhong Yu	Parasitic Parameter Extraction and Wire-Bonding Optimization for Cascode GaN FET in A New TO-247-4L Package	Power Electronics	ACCEPT
588	Jun Xiao, Run Shao, Wenguo Ning, Jing Wang and Yongchao Fu	Failure Analysis and Improvement of b-HAST for eMMC Products	Quality & Reliability	ACCEPT

Paper ID	Authors	Title	Track	Decision
589	Xuewei Zhao, Ruiyang Zhou, Yilin Ma, Yanqiang Yang, Yang Pang and Fanchen Meng	Thermal Reliability Study of TSV Structures for Flip-Chip MEMS Inertial Devices	Quality & Reliability	ACCEPT
590	Shengnan Li, Yafei Wang and Hong Li	High-Performance Epoxy Molding Compound Localization: Technological Breakthrough and Industrial Validation for Semiconductor Supply Chain Autonomy	Quality & Reliability	ACCEPT
593	Zhen-Tao Yang	Research on a High Reliability CQFN Package with a Pitch of 0.50 mm at 50 GHz	RF Electronic Packaging	accept?
597	Qingxin Liu, Kailin Ren, Luqiao Yin and Jianhua Zhang	Monolithically Integrated Voltage Reference Based on p-GaN/AlGaN/GaN Heterostructure	Power Electronics	ACCEPT
599	Qiunan Shi, Junjie Li, Kaihou Wang, Yatian Tang, Zhengbiao Zhang and Guoliang Xie	Wafer-level TSV package of TF-SAW filter built by low-stress silicon-cap epoxy bonding	Advanced Packaging	ACCEPT
600	Hengtong Guo Hengtong, Shimeng Xu, Xiaochen Xie, Pengrong Lin, Jianzhong Li and Changhao Chen	Research on High Reliability Copper Pillar Micro Convex Interconnection Technology for Aerospace Chip Integration	Interconnection Technologies	ACCEPT
601	Patrik Carazzetti, Carl Drechsel, Jürgen Weichart, Kay Viehweger and Ewald Strolz	Development of a Highly Sensitive Test Vehicle for the Accurate Measurement of Seed Layer Contact Resistance in 2.0 µm-diameter Vias	Advanced Packaging	ACCEPT
602	Cai Ning, Chen Zelin, Guo Zhenyi, Cai Peimian and Liao Wugang	Thermal Modeling and Characterization of Coaxial Through Silicon Via for 3D RF Integrated Circuits	RF Electronic Packaging	ACCEPT
603	Yuchen Wei, Leyin Zhang, Susu Li, Han Jiang, Zhihong Zhong, Yaohua Xu and Shuibao Liang	Unraveling Grain Boundary Migration and Evolution of the Cu-Cu bonding Structure Driven by Thermo-mechanical Stress	Interconnection Technologies	ACCEPT
604	Hao Zhang, Xing Jin, Bin Wang, Jian Xiang, Jian Wang, Rui Tang and Xiaoqiang Wang	Degradation Mechanism Induced by High-Energy Hot Electrons in GaN MMIC Power Amplifiers under High Drain Bias Stress	Quality & Reliability	ACCEPT
606	Hao Fu, Zhu Yang, Hong Fan, Xinhui Meng, Xiuzhen Lu, Luqiao Yin and Jianhua Zhang	Simulation and Experimental Validation of Bonding Between Copper Pillar Bumps and Micro-LED	Optoelectronics and New Display	ACCEPT
607	Lianyu Wang, Kailin Ren, Luqiao Yin and Jianhua Zhang	Study of Cu/Al2O3 hybrid bonding process based on atomic layer etching	Advanced Packaging	ACCEPT
609	Lixiang Zhang and Xuejiao Zhang	The influence of vacancy defects on the interface thermal resistance of diamond based GaN RF device	Emerging Technologies	ACCEPT
611	Renzhe Li, Feixuan Huang, Chen Ma, Feiya Suo, Xudong Xu, Ziyi Ge, Xitong Wang and Nan Wang	Spurious Mode Suppression of Thin-Film Lithium Niobate A3 Mode Lamb Wave Resonators	RF Electronic Packaging	ACCEPT

Paper ID	Authors	Title	Track	Decision
612	Xuewei Zhao, Nannan Li, Zhiqiang Gao, Deyan Wang, Xiao Ma and Zihan Nan	Failure Mechanism of the Si-TSV Structure Under Temperature and Radiation Synergistic Effects	Quality & Reliability	ACCEPT
613	Huan Liu, Zhijun Lv, He Jiang and Fei Wang	Development of High-performance Silicon-based MEMS Bandpass Filter	RF Electronic Packaging	ACCEPT
614	Haoran Ma, Min Gou, Xinxu Zhang, Shiyu Chen and Meng Sun	Simulation and Design of the 3D Silicon Capacitor Structure Charactered by Low-Parasitic, High-Capacitance and High-Reliability	RF Electronic Packaging	ACCEPT
615	Jinyang Zhao, Lixin Zhan, Xinpeng Chen, Yaru Zhang and Baoxia Li	Void Defect Analysis and Mitigation in Underfill Process of PoP Flip-Chip Packages: A Multiphysics Modeling and Experimental Investigation	Advanced Packaging	ACCEPT
616	Xiaoyue Duan, Panpan Jiang, Liang He, Yijun Shi, Xinghuan Chen, Zhiyuan He, Yuan Chen and Yiqiang Ni	Hydrogen effects on enhanced-mode AlGaN/GaN MOSFET with Al2O3 gate dielectric	Quality & Reliability	ACCEPT
617	Yufei Bai, Xiaoyun Qi, Jia Yang and Chenxi Wang	A Novel NH4OH-assisted Self-Aligned Cu/SiO2 Bonding for High-Precision and High-Speed Hybrid Bonding.	Interconnection Technologies	ACCEPT
618	Siyi Jing, Yifan Yao and King-Ning Tu	Effect of Interfacial Cracks between TSV and RDL on Electromigration Reliability	Quality & Reliability	ACCEPT
619	Liangxing Hu, Huaiyun Fan, Xin Zhang, Yongfa Dong, Yaobin Li, Hesheng Tan, Yaqing Li, Huabing Deng, Yanyun Zhang, Nan Wang and Kai Tao	Time-Dependent Evolution Study of Plasma-Treated Al Surface Enabling Two-Step Al-Al Direct Bonding in Ambient	Interconnection Technologies	ACCEPT
620	Xiangyu Ren and Yunwen Wu	Develop self-forming conformal multifunctional interconnect layer to meet the demands of advanced Cu interconnect	Interconnection Technologies	ACCEPT
621	Chenghao Bei, Tian Yu, Shuting Wang and Daquan Yu	Research on Thermal Stress Analysis of Glass-Based Deep Trench Capacitor	Quality & Reliability	ACCEPT
622	Lin Daotan, Wu Huiwei and He Guanghui	Research on Construction Analysis Method of 3D Stacked Chips Based on Failure Mechanism	Quality & Reliability	ACCEPT
623	Xinpeng Chen, Yaru Zhang, Lixin Zhan, Jinyang Zhao and Baoixa Li	Research on 3D Assembly Process Based on Wafer-Level Electroplated Microbump Structures	Advanced Packaging	ACCEPT
624	Qian Zhou, Donghua Yang, Jun Luo, Bin Jiang, Zhenhua Wang, Chunhong Zhang and Kailun Hu	Multicomponent Alloy Design and Performance Optimization of Sn-In-Ag-Al-Zn Solder alloys	Packaging Materials & Processes	ACCEPT
625	Yuting Liang, Junpeng Fang, Qian Wang, Jian Cai, Yao Zheng, Haiyan Ma and Yalu Chen	Structural Evolution of Chip to Chip Hybrid Bonding Interface after Temperature Cycling and High Temperature Storage Tests	Interconnection Technologies	ACCEPT

Paper ID	Authors	Title	Track	Decision
626	Longsheng Fang, Wei Shen, Mengyun Zhang, Shimiao Wang and Tao Hang	Texture Modulated Cobalt Film with Improved Soft Magnetic Properties for Low-loss High-frequency Signal Transmission	Packaging Materials & Processes	ACCEPT
627	Wei Zhang and Liang Ren	Active Thermography for Quantitative Assessment of Solder Fill Height in Through-Hole Interconnects: A Coupled Numerical-Experimental Investigation	Packaging Design & Modeling	ACCEPT
628	Yik Fan Chen, Zirou Chen and Jun Wang	Influence of Underfill and EMC Material Properties on Bump Thermal Stress in 2.5D CoWoS Structure	Packaging Materials & Processes	ACCEPT
629	Xu Han, Fang Dong, Chengliang Sun and Sheng Liu	A high uniform electric field in drift region with array structure 4H-SiC LDMOS	Power Electronics	accept?
630	Sichen Liang, Zhiheng Huang, Kaiwen Zheng, Min Xiao, Yuezhong Meng and Yang Liu	Microstructural Hierarchy Data Insights from Ag Paste and Cu-Cu Hybrid Bonding	Interconnection Technologies	ACCEPT
631	Yuke Jin, Zhu Yang, Xinhui Meng, Hao Fu, Luqiao Yin, Xiuzhen Lu and Jianhua Zhang	Thermo-Mechanical Coupling Simulation of Laser-Based Mass Transfer for Micro-LEDs	Optoelectronics and New Display	ACCEPT
634	Feiya Suo, Feixuan Huang, Chen Ma, Renzhe Li and Nan Wang	Spurious Mode Suppression in Lamb Wave MEMS Resonators Based on 128°Y-Cut LiNbO3/SiO2	RF Electronic Packaging	ACCEPT
636	Xitong Wang, Jiewei Jiang, Chen Ma, Zhiyu Wang, Feixuan Huang, Renzhe Li, Ziyi Ge, Chunmiao Qi and Nan Wang	High-Coupling and Lithographic Frequency Tunable Solidly Mounted Resonator (SMR) with Alternating Polarity-Inverted Piezoelectric Layer	RF Electronic Packaging	ACCEPT
637	Bofu Li, Baorong Su, Shunfeng Han and Miao Cai	WBLGA SiP High-Reliability and High-Thermal Conductivity Design Optimization and Interconnect Process Exploration	Optoelectronics and New Display	ACCEPT
638	Yan Yan, Feifei Huang, Jing Ren and Mingliang Huang	Study on synergistic effect of additives for wafer-level electroplating of Sn-Ag micro-bumps	Interconnection Technologies	ACCEPT
639	Ran Liu, Zheng Zhang, Masahiko Nishijima, Chuantong Chen, Hirokatsu Sakamoto, Akihiko Happoya and Katsuaki Suganuma	Advancing Microelectronic Packaging Performance through Cu Paste Technology	Advanced Packaging	ACCEPT
641	Fengrui Zhang, Feifei Huang, Jing Ren, Yan Yan, Lipeng Zheng and Mingliang Huang	Effect of additive adsorption on Sn-Ag micro-bump electroplating	Interconnection Technologies	ACCEPT
642	Yichi Zhu and Jun Wang	Double-Layer Coolant System Using Microchannel with Adaptive Fins for High-Power Electronics	Packaging Design & Modeling	ACCEPT
644	Mengmeng Wang, Haoran Bian, Yuefang Li, Yuanpeng Li and Hua Zhong	Investigations on Surface Insulation Reliability of Ceramic Substrates	Quality & Reliability	ACCEPT

Paper ID	Authors	Title	Track	Decision
645	Ki-Cheol Kim, Chung-Ha Jung and Gu-sung Kim	Comparative study of thermal stress in TGV structure with various aspect ratio.	Advanced Packaging	ACCEPT
646	Mingjie Lee, Yang Liu, Yun Wu and Xiuzhen Lu	Mechanical properties and reliability of Cu Pillar Micro-bump Interconnect for Micro-LED Integration	Optoelectronics and New Display	ACCEPT
647	Yuxiang Tian, Jiarui Qiu, Yiqin Xiang and Hanzhi Ma	Fast Liquid Neural Network-Based Signal Integrity Analysis for Heterogeneous Integration System in Display	Optoelectronics and New Display	ACCEPT
648	Chaoxi Shu, Zhiwen Chen, Li Liu and Sheng Liu	First-Principles Study of Temperature-Dependent Exciton-Phonon Coupling in AlN	Optoelectronics and New Display	ACCEPT
650	Chenshan Gao, Shizhen Li, Shenglin Zhang, Hanshi Wang, Ke Liu, Yuqi Wang, Chunjian Tan, Lingen Wang, Guoqi Zhang, Shaogang Wang and Huaiyu Ye	Finite Element Optimization of Thermal-Mechanical Coupling in Smart P2 Pack Frontal Interconnects	Power Electronics	ACCEPT
651	Jiayao Fan, Haoshen Zhu, Junjie Liao and Shaowei Liao	Accurate Material Characterization on HDI PCB with Heterogeneous Layers for mmW applications	Packaging Design & Modeling	ACCEPT
652	Mian Tao, Ji Shu, Kevin J. Chen and Ricky S. W. Lee	Thermal Mechanical Simulation Analysis of 3D Stacking Co-packaged GaN/SiC Device	Power Electronics	ACCEPT
654	Young-Joo Park, Jong-Bum Lee, Seung-Boo Jung and Kwang-Seok Kim	Enhanced Mechanical Reliability of Sn-57Bi-1.0Ag Solder Joints by Intense Pulsed Light Soldering under Thermal Aging	Packaging Materials & Processes	ACCEPT
659	Jin Bee Park and Min Hyung Kang	LTCC Warpage Reduction via Interlayer Shrinkage Mismatch Control for RF Electronic Packaging	Quality & Reliability	ACCEPT
660	Min Hyung Kang and Jin Bee Park	Controlling Intermetallic Compound Growth of Solder Joints for Robust Semiconductor Interconnects	Interconnection Technologies	ACCEPT
661	Min Hyung Kang	Thermal Management Packaging for Wearable Optoelectronics via Nano-/Micro-Voids Polymer(NMVP) Integration	Emerging Technologies	ACCEPT
662	Yachao Liu and Bin Ren	Modified Composite Nonlinear Active Disturbance Rejection Control Method for Linear Motion Platforms in High-Speed Wire Bonding Machines	Advanced Manufacturing	ACCEPT